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1

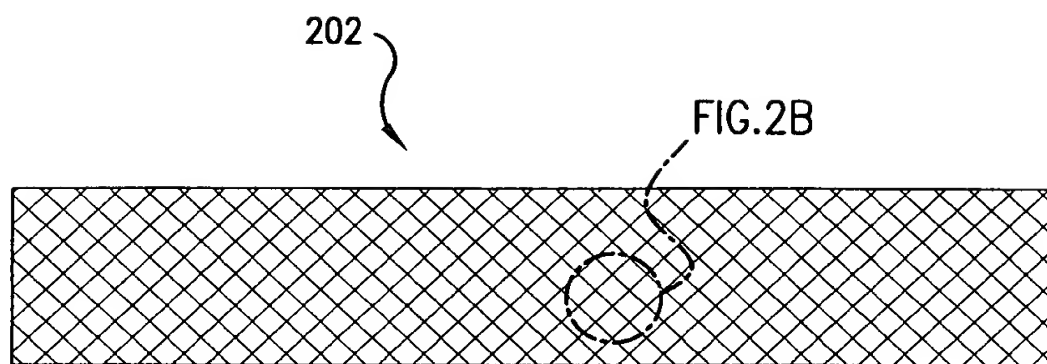


FIG. 2A

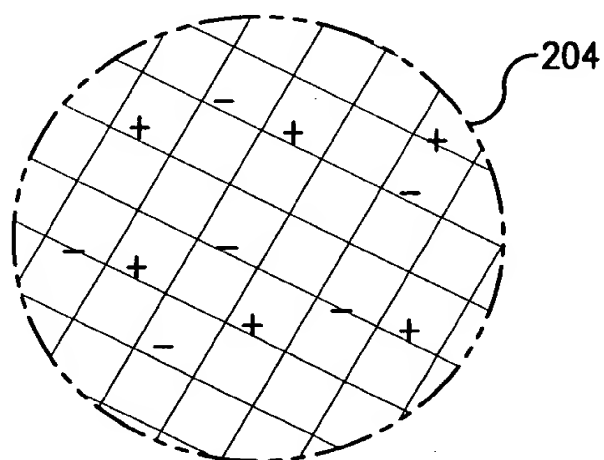


FIG.2B

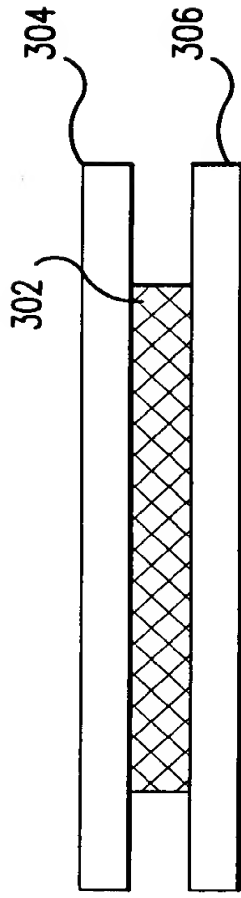


FIG.3

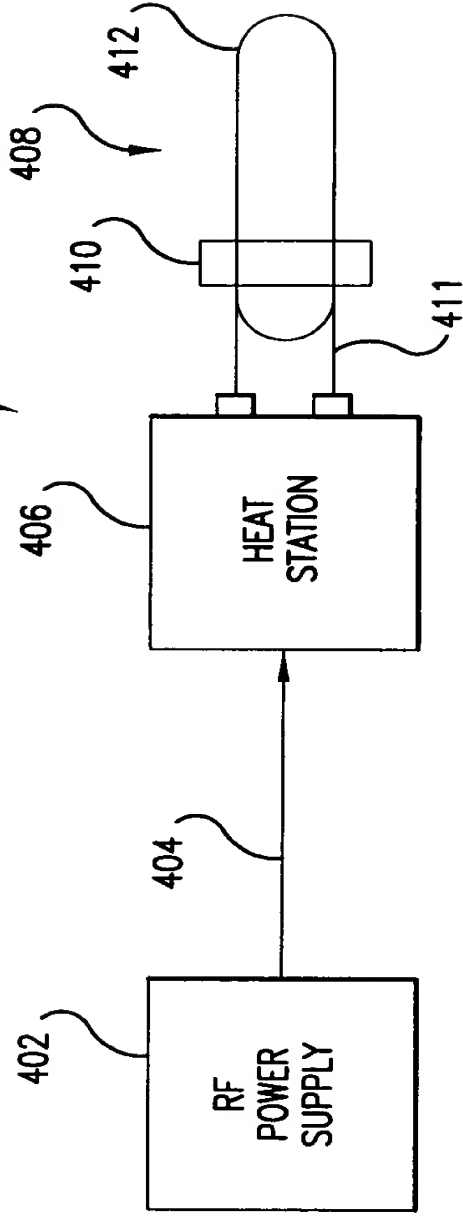


FIG.4

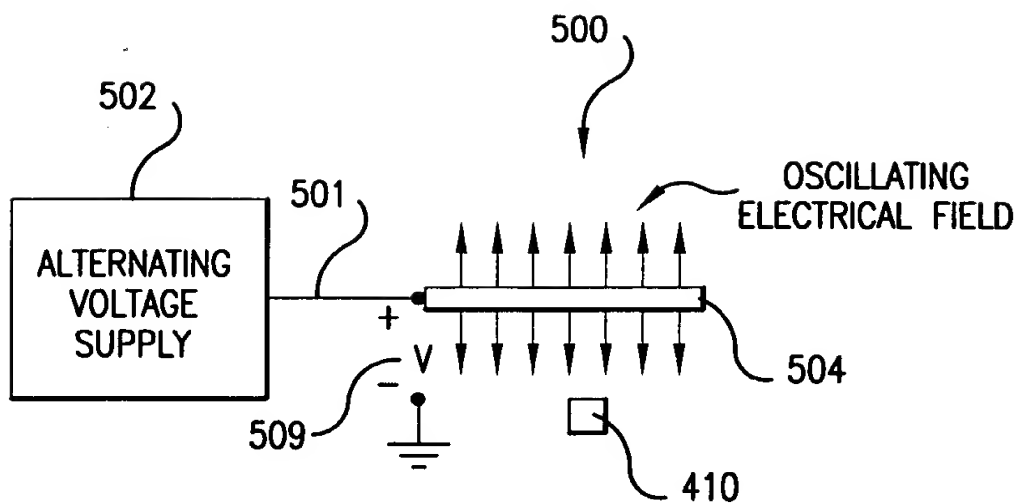


FIG.5

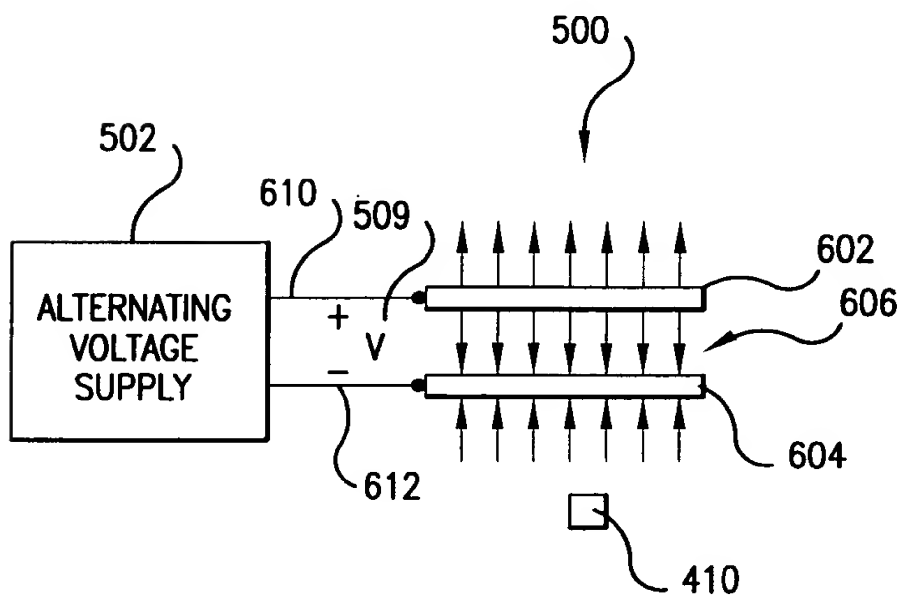
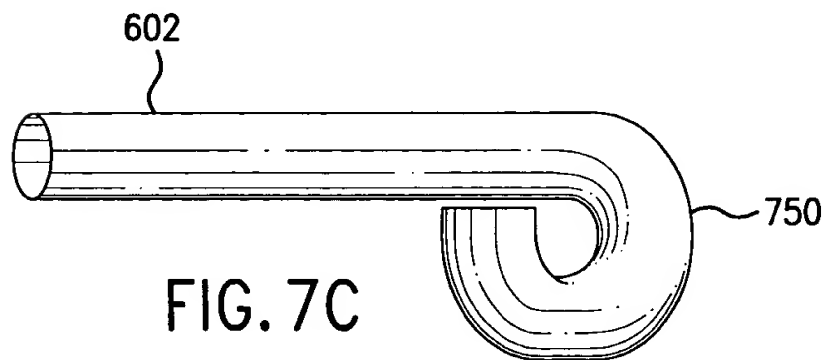
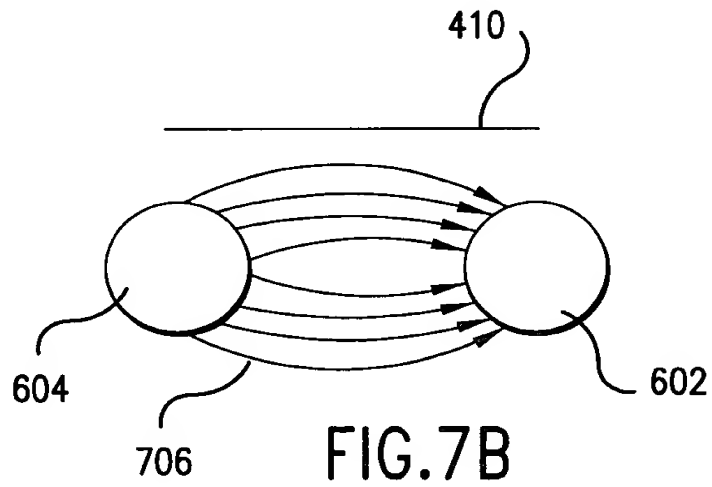
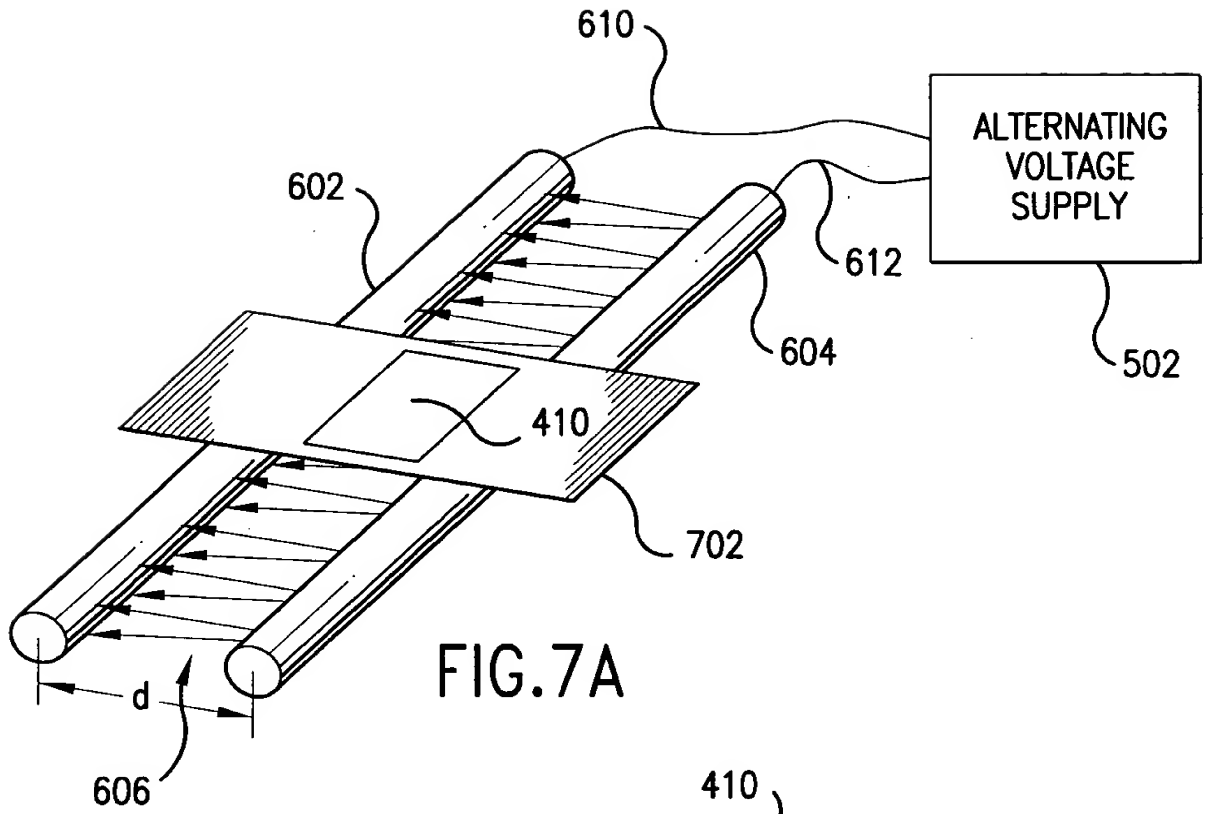


FIG.6

002260" 0249860



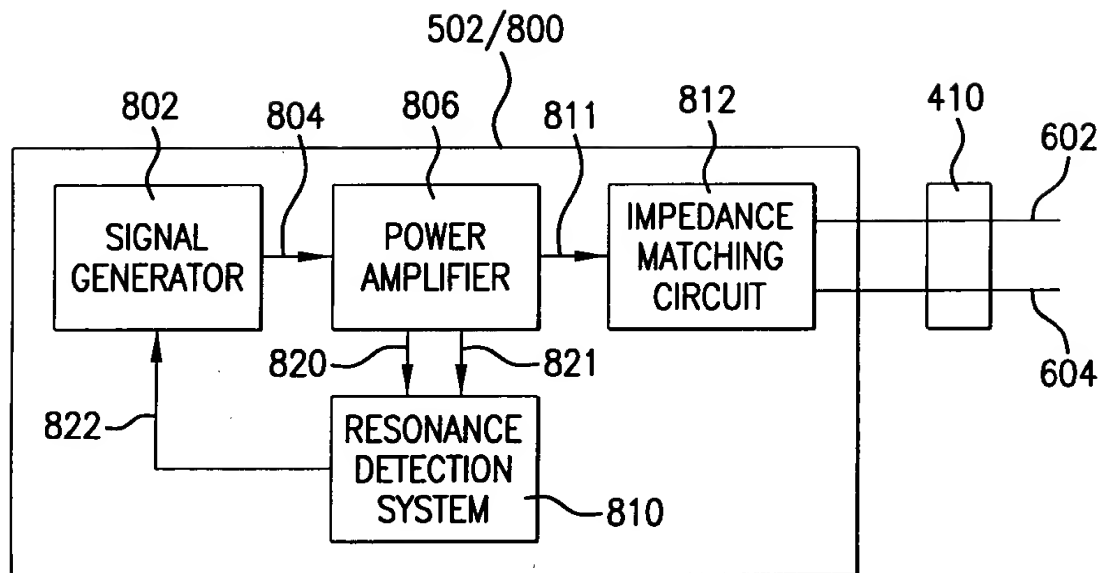


FIG.8



FIG.9

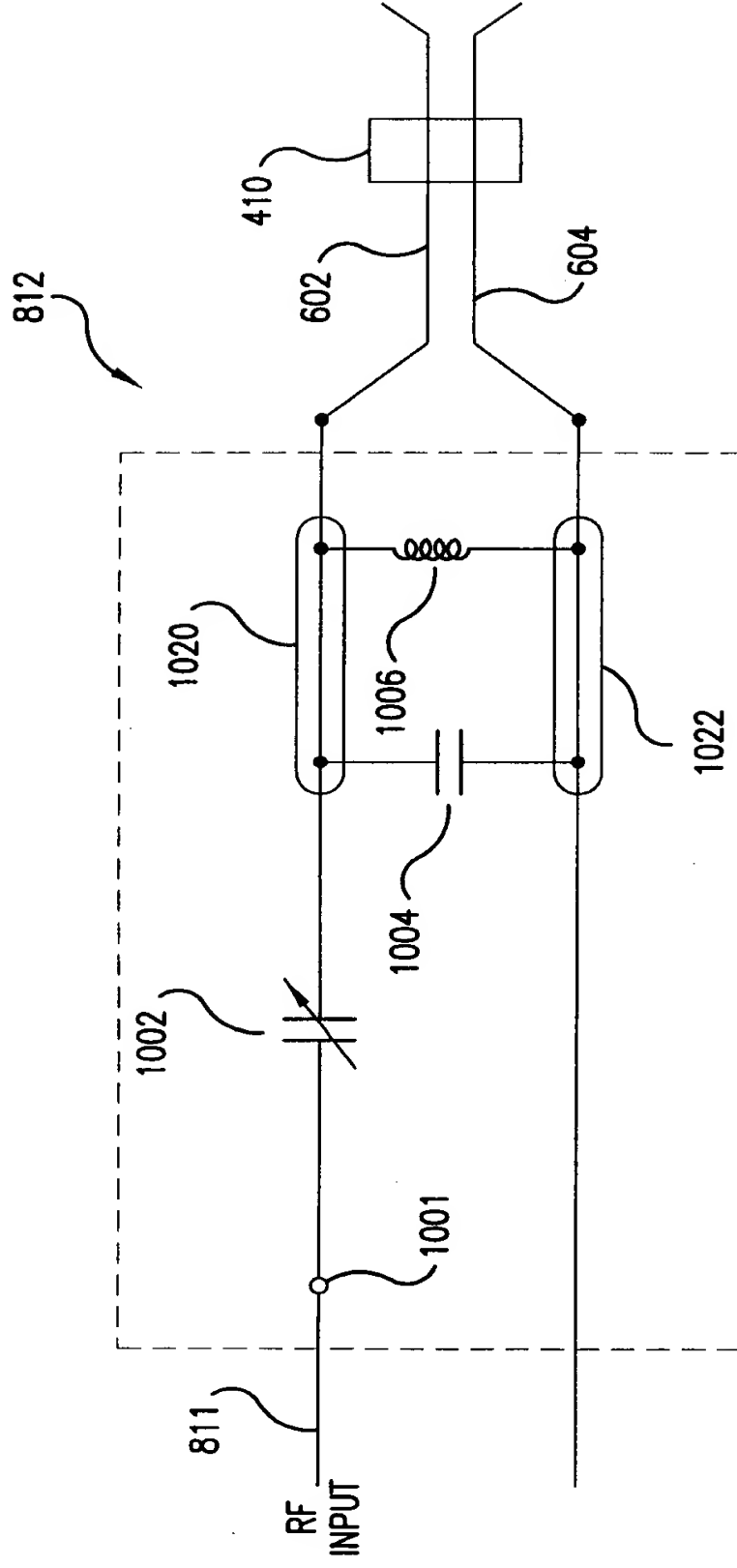


FIG. 10A

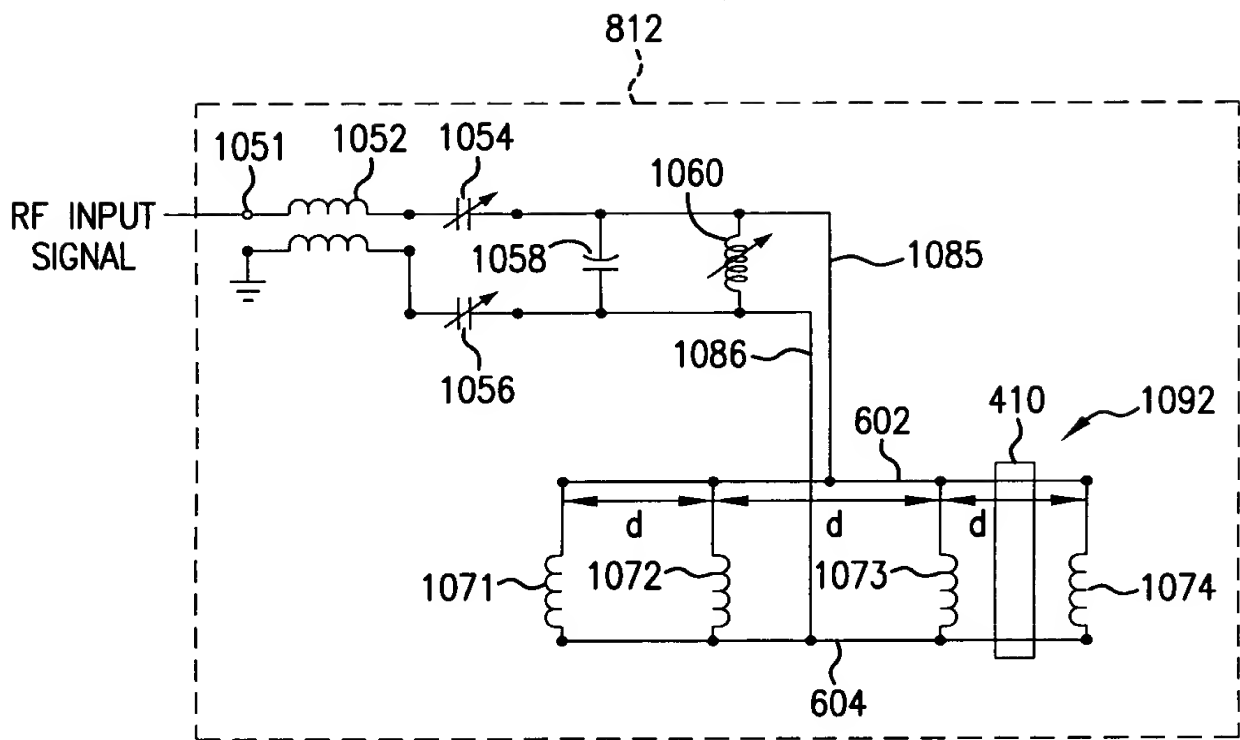


FIG.10E

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graph TD
    1102[CHOOSE LAYERS TO BE BONDED OR ADHERED] --> 1104[CREATE SUSCEPTOR MIXTURE]
    1104 --> 1106[SATURATE INSOLUBLE POROUS CARRIER WITH SUSCEPTOR MIXTURE]
    1104 --> 1109[MAKE A FILM OF SUSCEPTOR ADHESIVE]
    1104 --> 1110[COAT FIRST AND/OR SECOND LAYERS WITH SUSCEPTOR COMPOSITION]
    1106 --> 1108[PLACE SATURATED INSOLUBLE POROUS CARRIER BETWEEN FIRST AND SECOND SUBSTRATE LAYERS]
    1109 --> 1111[SANDWICH FILM BETWEEN TWO SUBSTRATES]
    1110 --> 1112[OPTIONAL WAIT FOR COATING TO DRY]
    1112 --> 1114[PLACE FIRST AND SECOND LAYERS WITH COATING(S) IN DIRECT CONTACT WITH ONE ANOTHER]
    1108 --> 1120[APPLY RF ENERGY]
    1111 --> 1120
    1114 --> 1120

```

FIG. 11

FIG.12

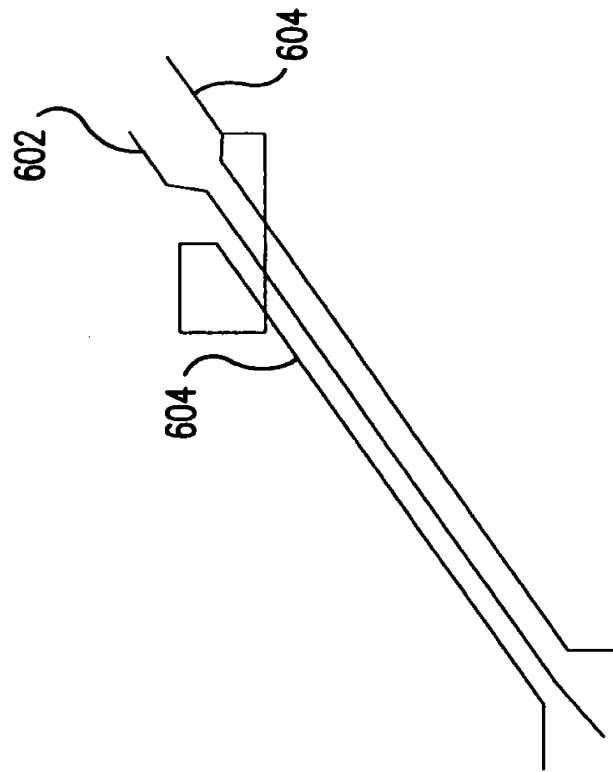


FIG. 13A

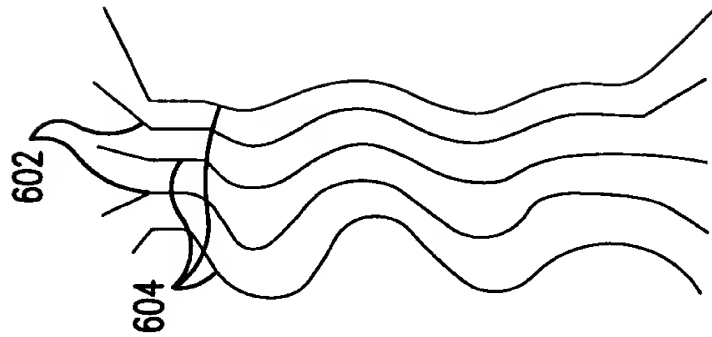


FIG. 13B

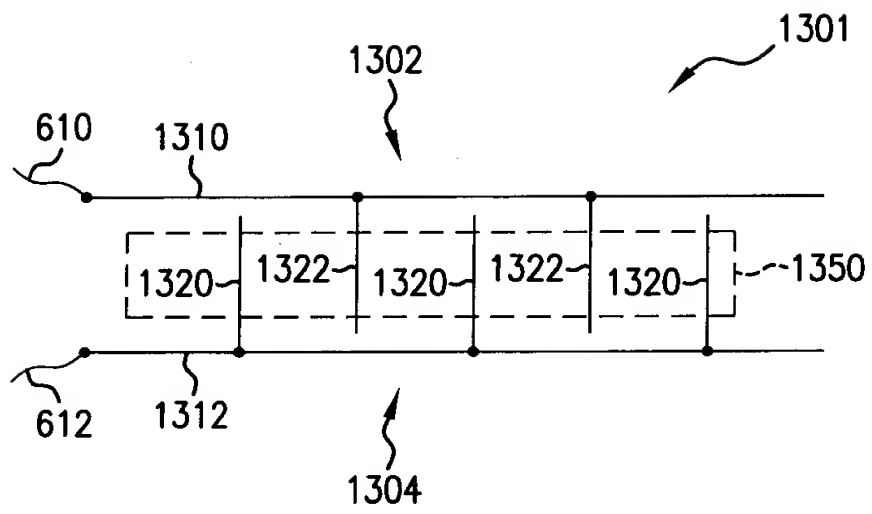
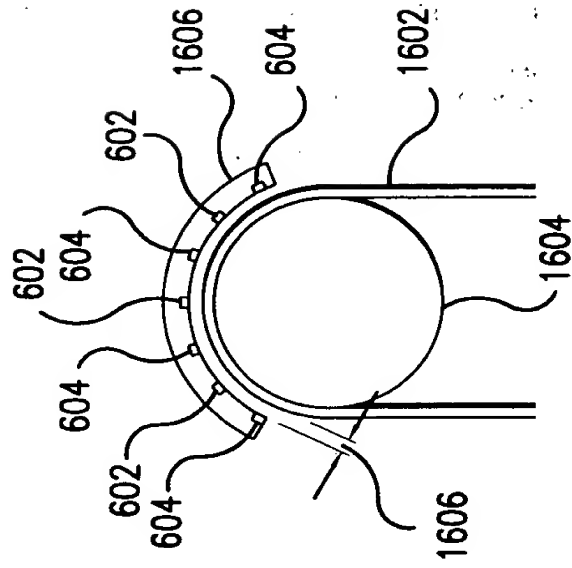
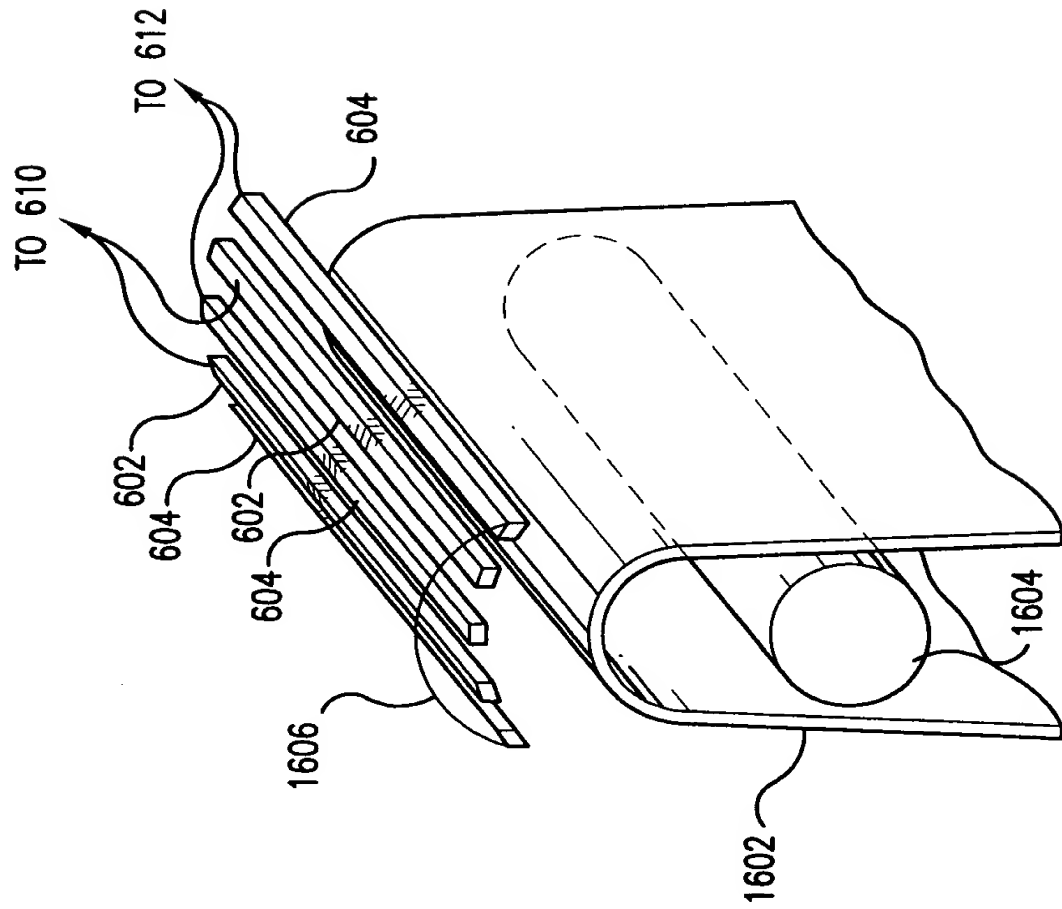


FIG.13C



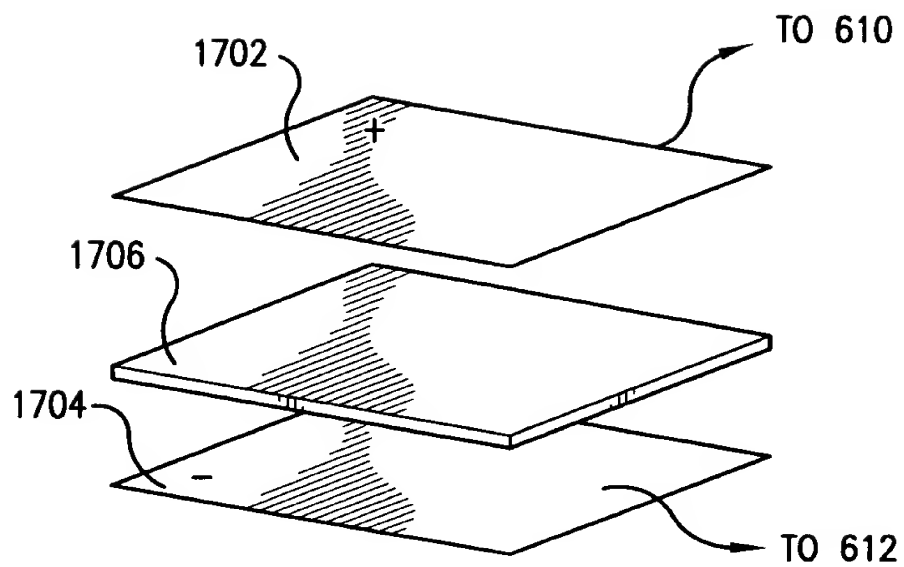


FIG.17

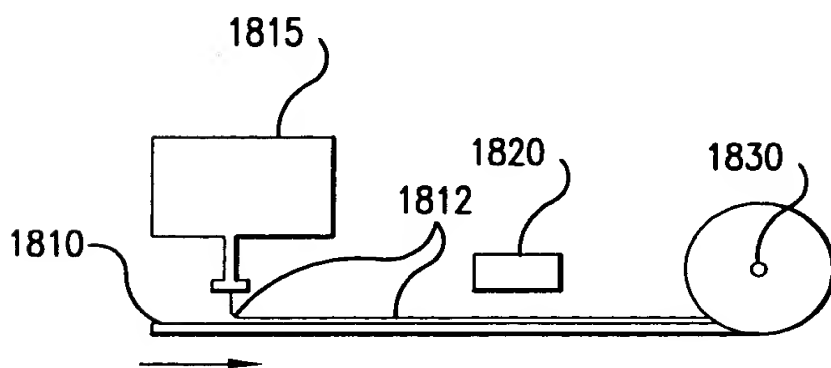


FIG.18

A cross-sectional view of a semiconductor device 2000. The device includes a substrate 2010 with a top surface 2012. A thin layer 2091 is formed on the top surface 2012. On top of layer 2091, there is a stack of layers 2090 and 2092. A vertical structure 2020 is formed on top of layer 2090. Two rectangular features 2006 and 2008 are formed on the bottom surface of the substrate 2010.

FIG.20B

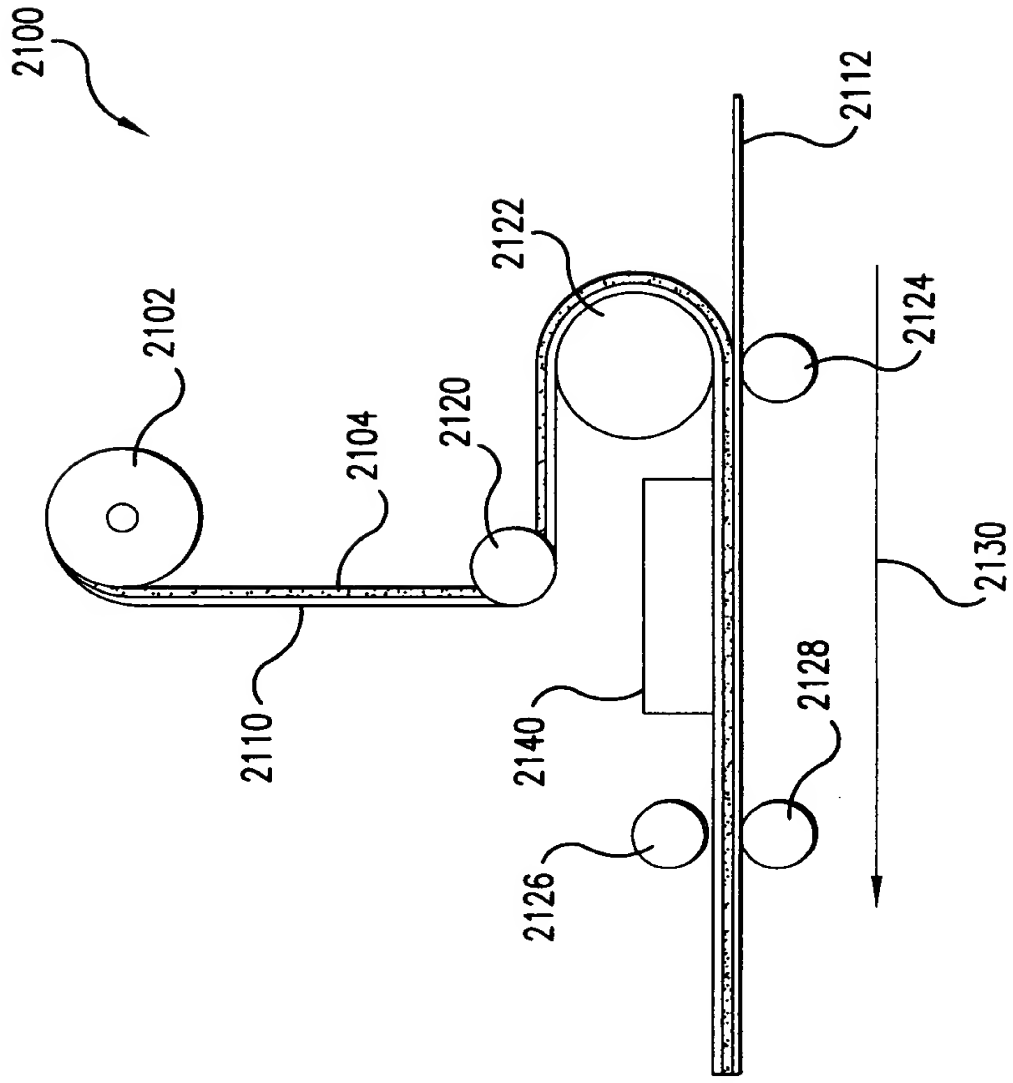


FIG.21

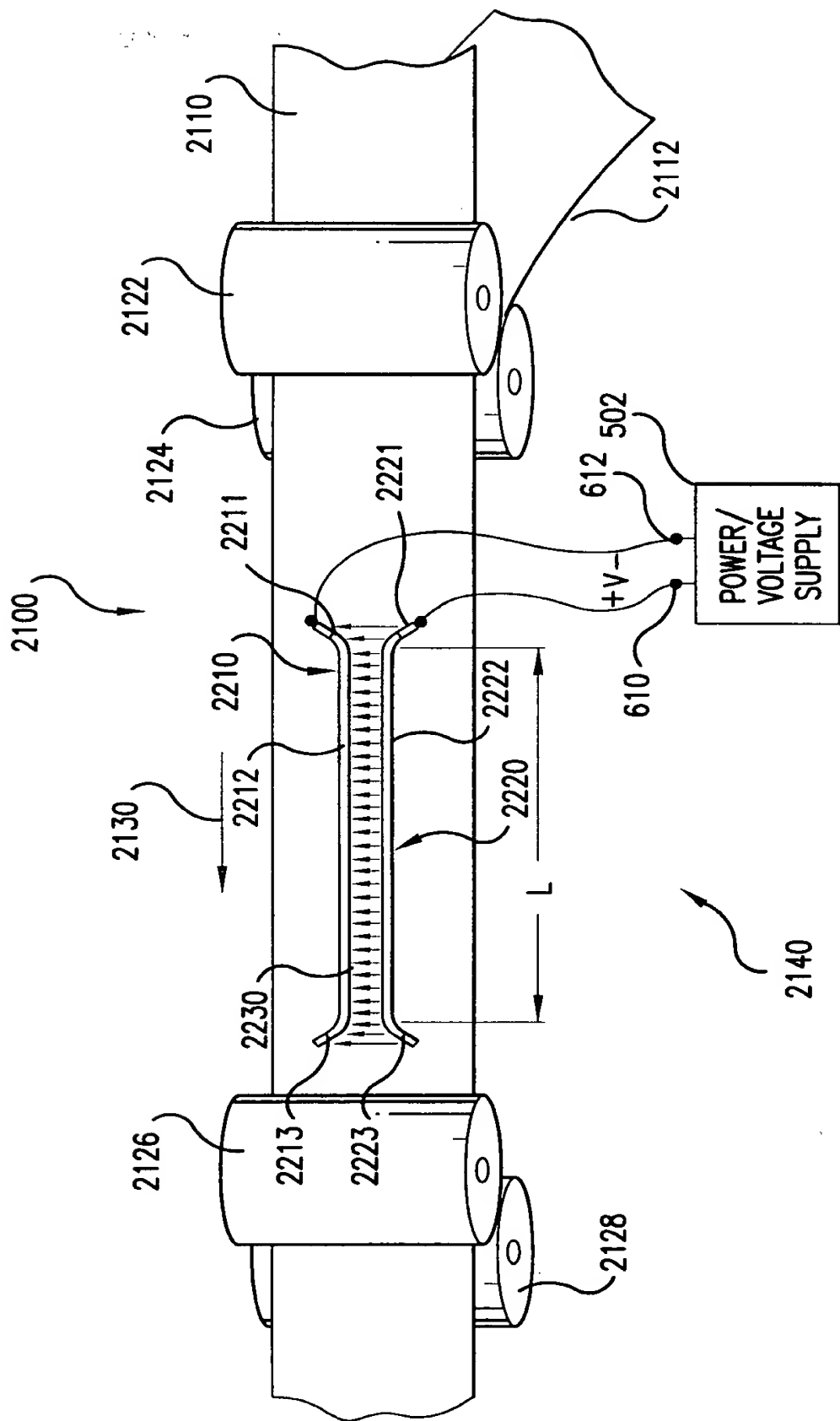


FIG. 22

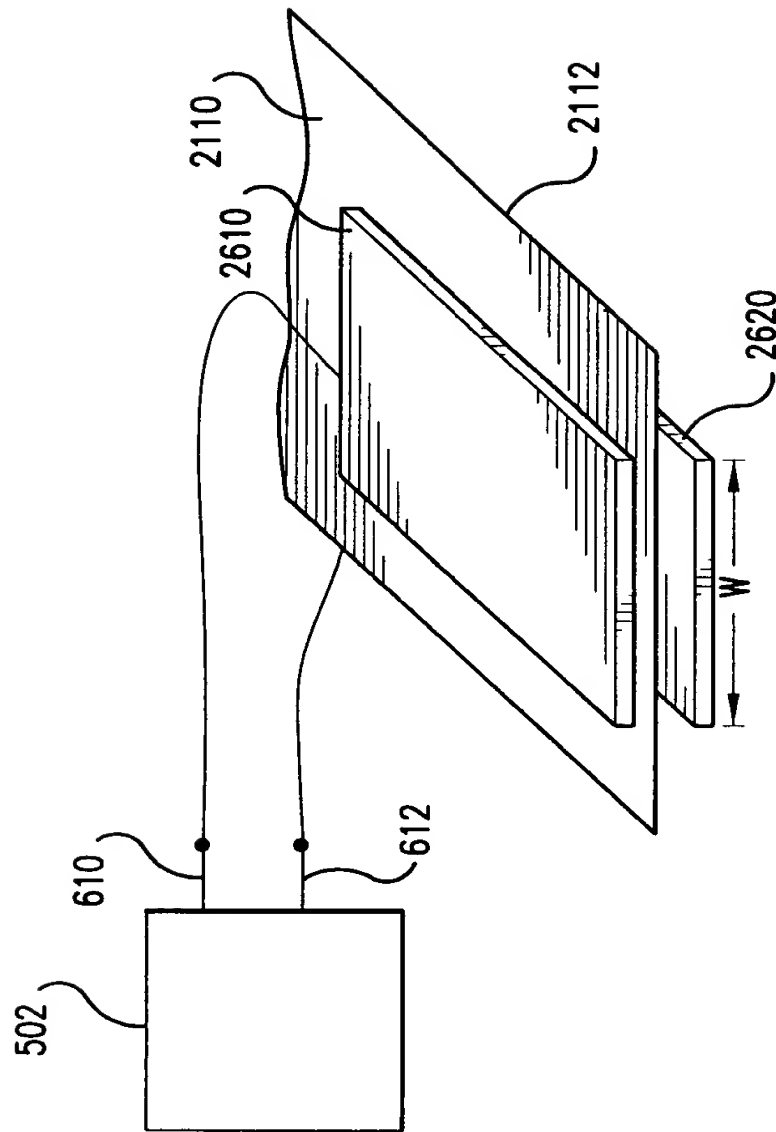


FIG.27

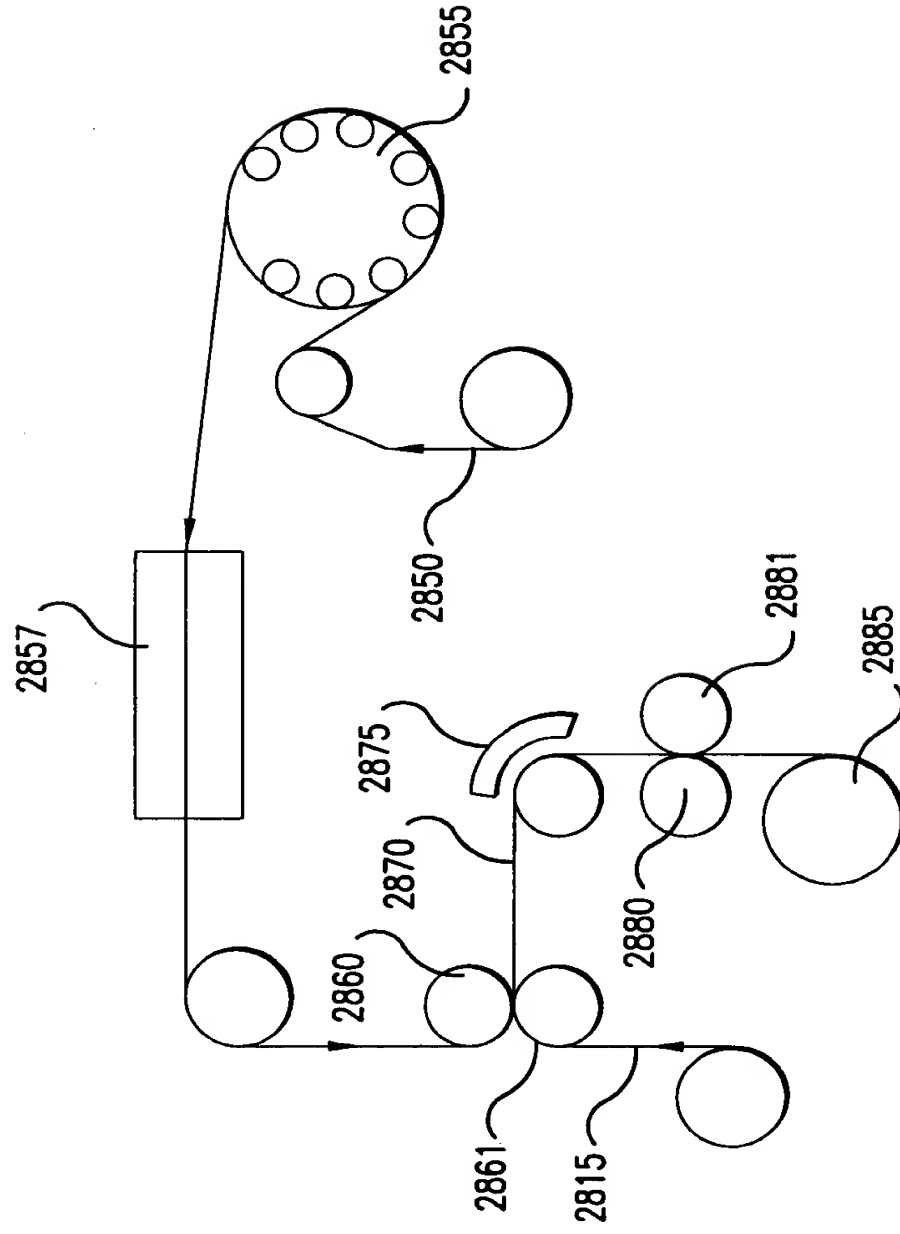


FIG. 28B

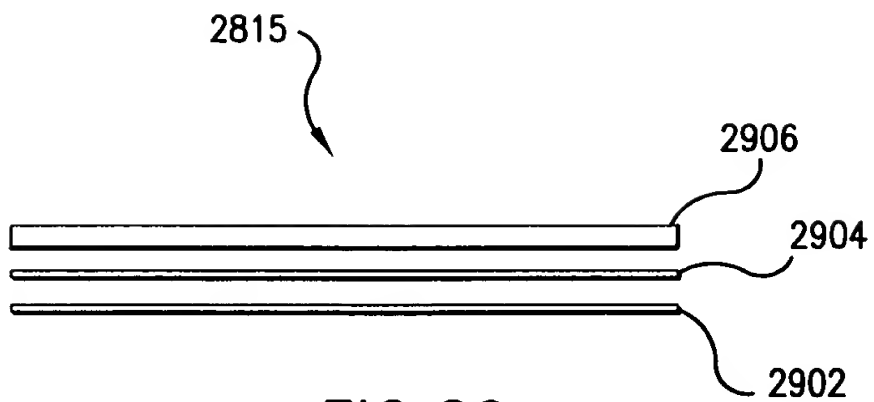
[illegible]

FIG.29

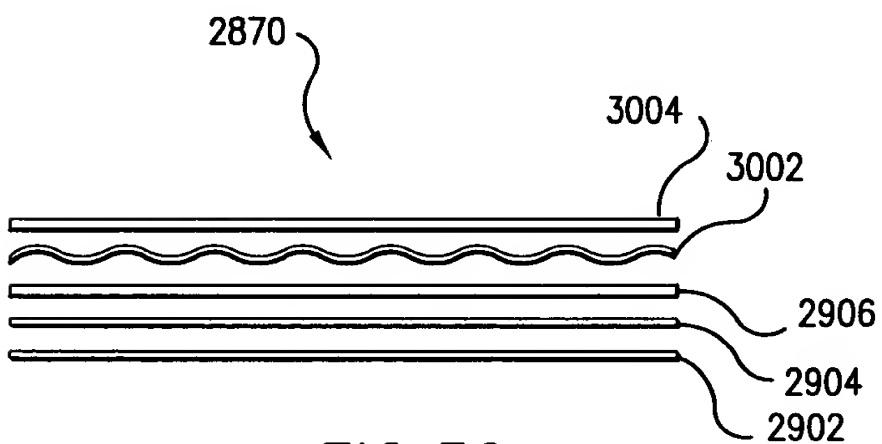


FIG.30

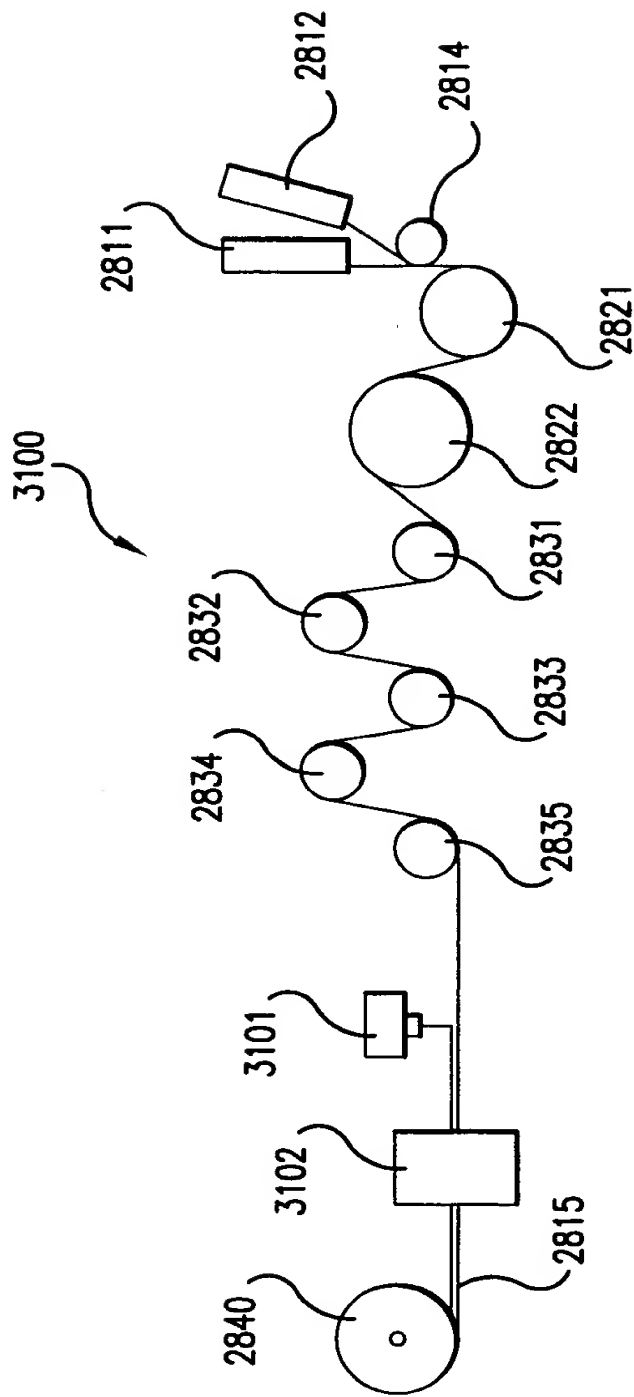


FIG.31

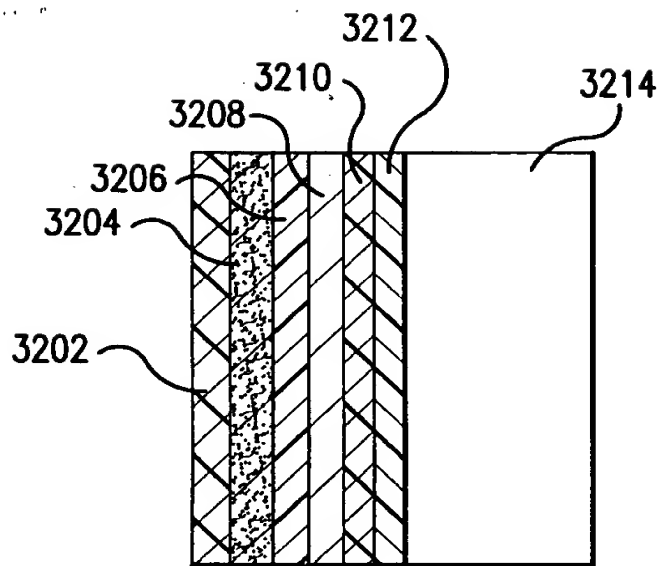


FIG.32

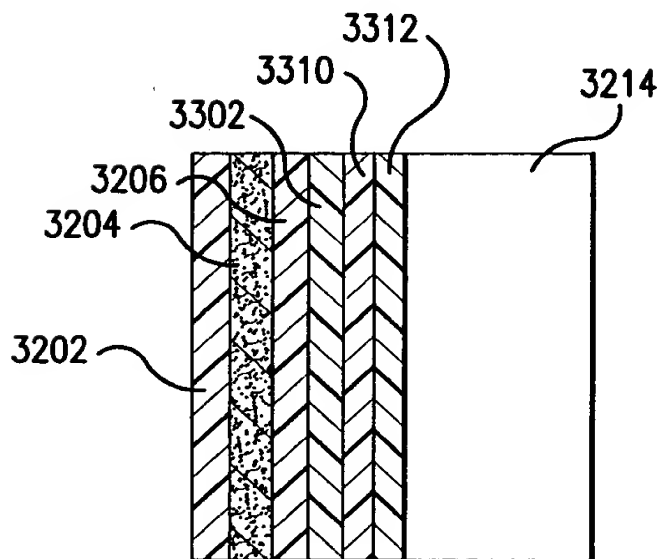


FIG.33

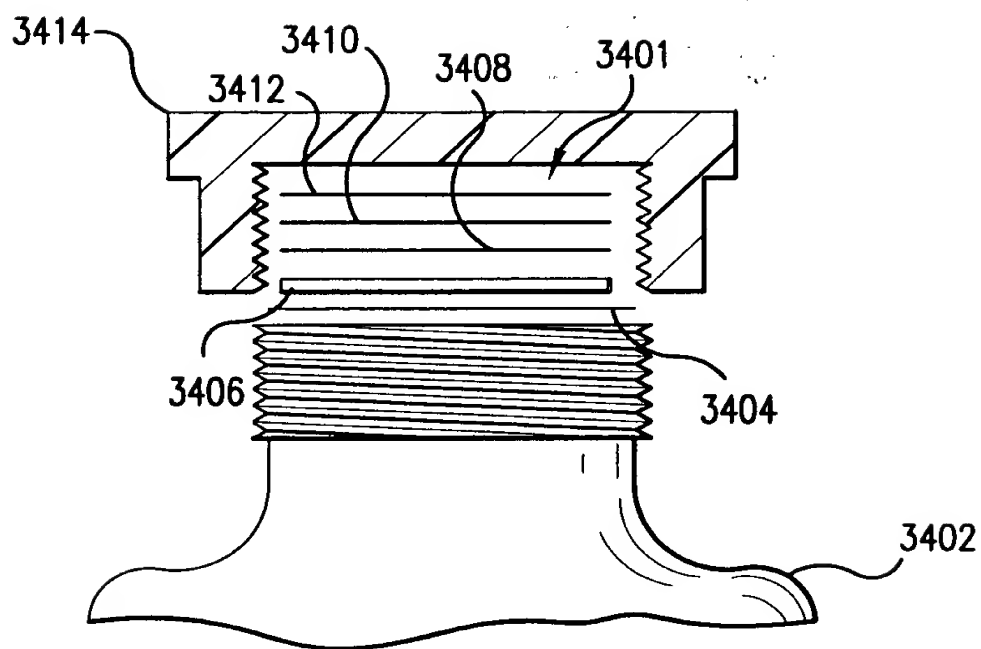


FIG.34

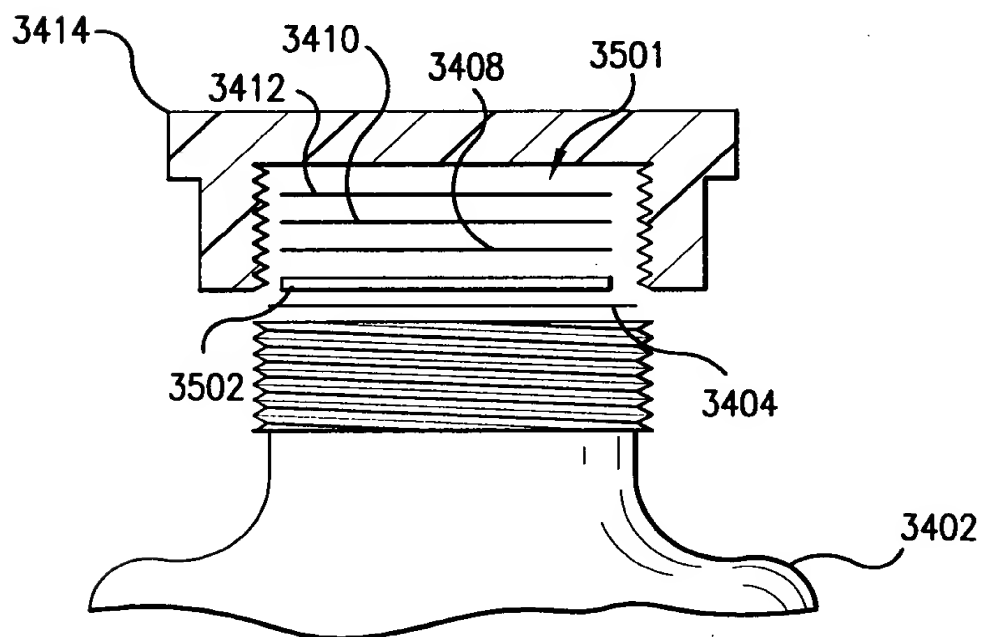


FIG.35

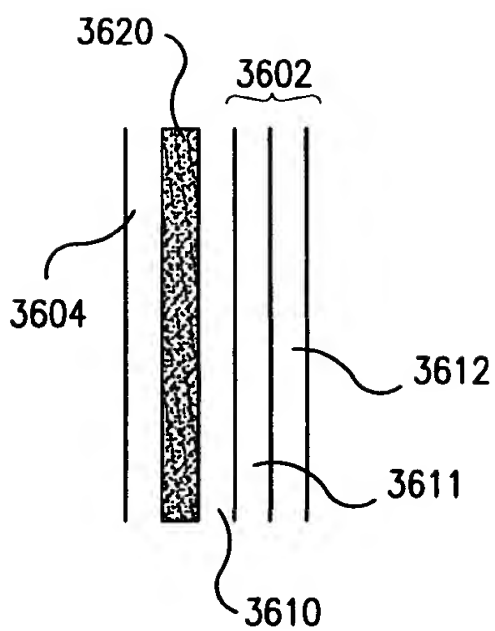


FIG. 36

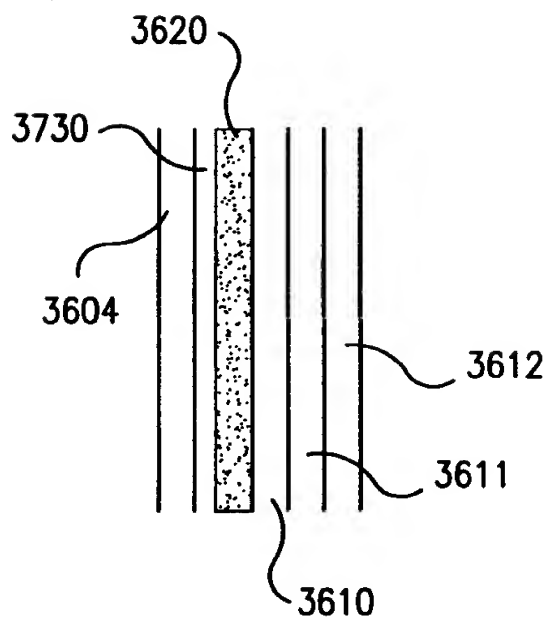


FIG. 37

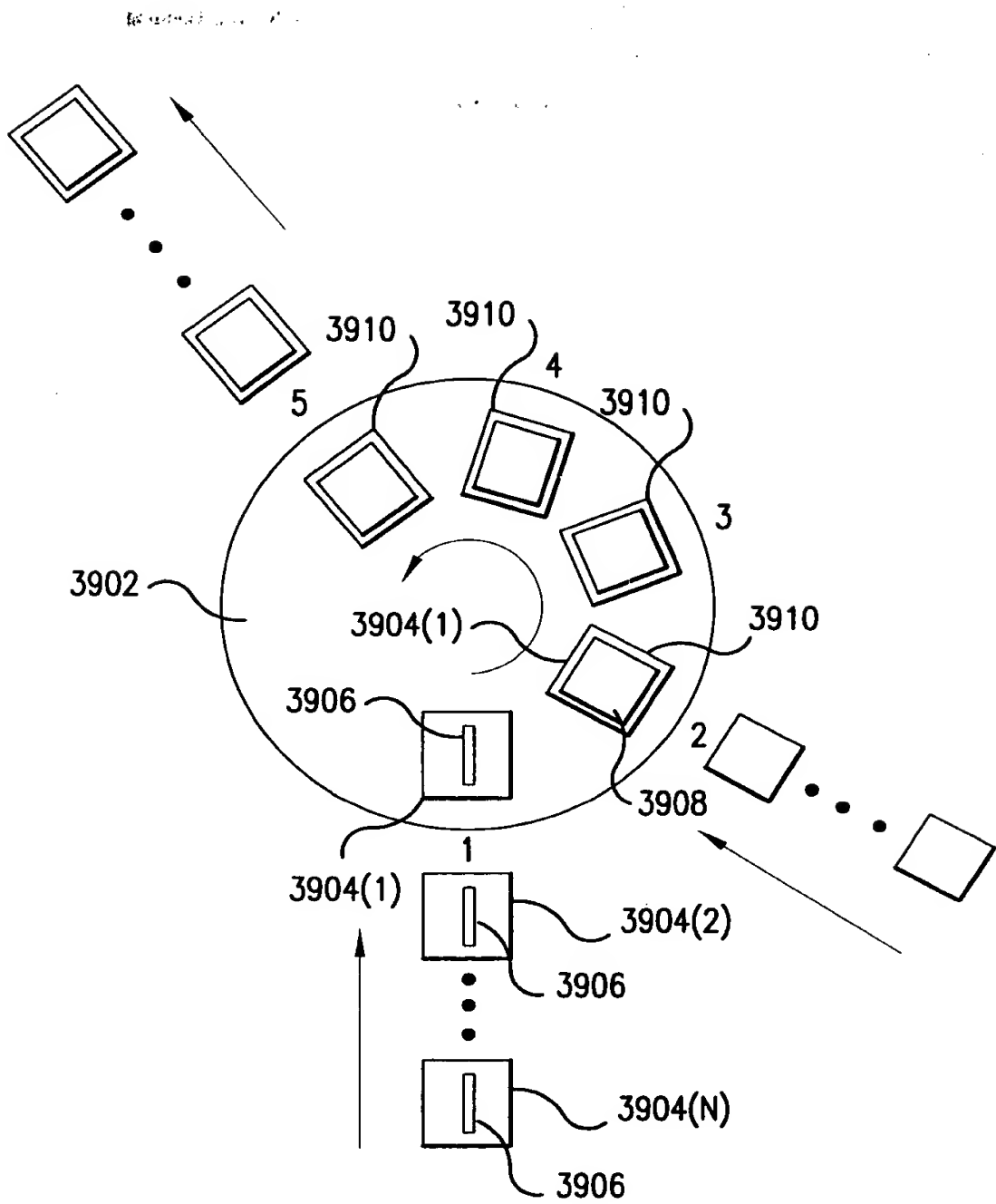


FIG.39

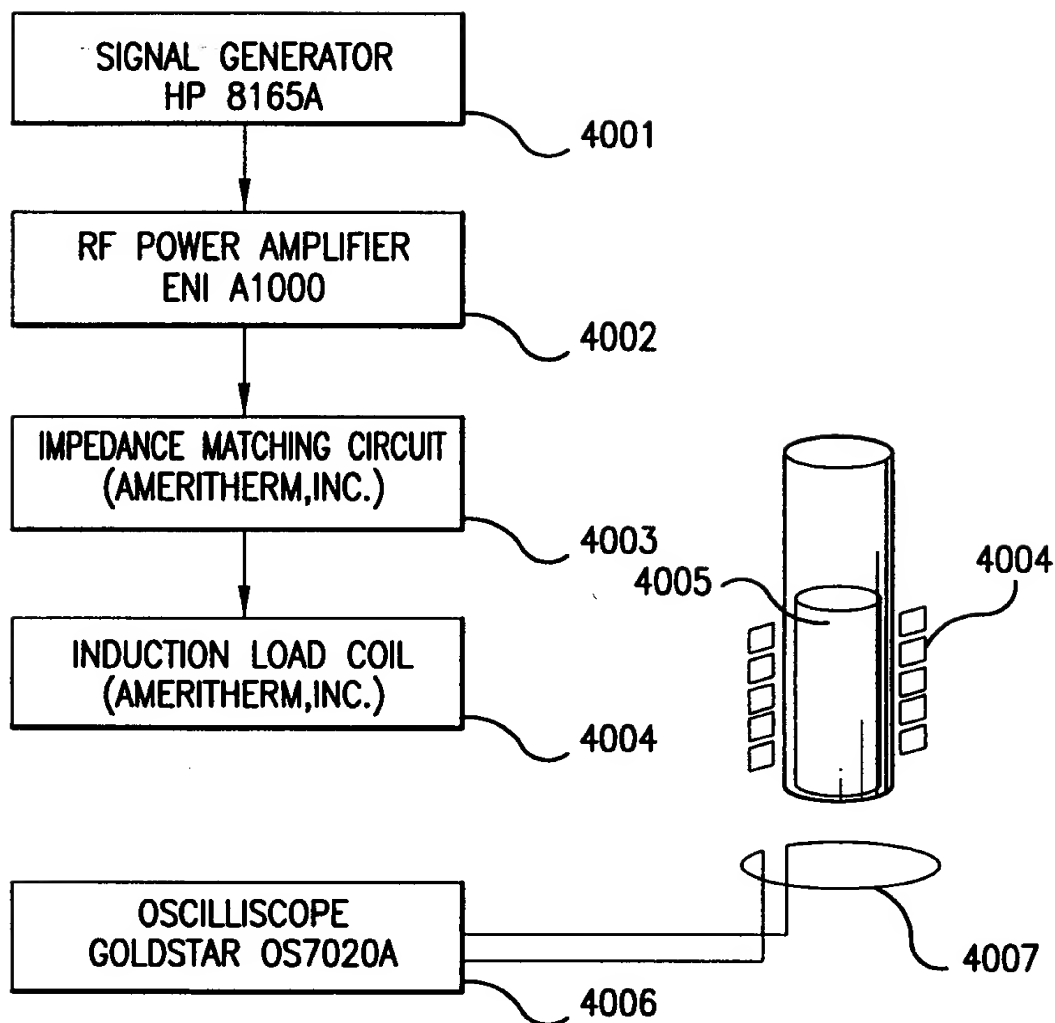


FIG.40


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graph TD; 4302[COAT A PORTION OF ONE SIDE OF A SUBSTRATE WITH A SUSCEPTOR COMPOSITION THAT FUNCTIONS AS AN ADHESIVE] --> 4304[ROLL THE SUBSTRATE OR CUT AND STACK THE SUBSTRATE FOR LATER USE]; 4304 --> 4306[FEED A COATED SUBSTRATE INTO A PRINTING MEANS FOR PRINTING INK ONTO THE SUBSTRATE]; 4306 --> 4308[STACK THE COATED SUBSTRATES AFTER PRINTING THEREON]; 4308 --> 4310[APPLY RF ENERGY TO THE STACK]; 4310 --> 4312[NIP THE STACK TO ASSURE A GOOD BOND];
```

4300

4302 COAT A PORTION OF ONE SIDE OF A SUBSTRATE WITH A SUSCEPTOR COMPOSITION THAT FUNCTIONS AS AN ADHESIVE

4304 ROLL THE SUBSTRATE OR CUT AND STACK THE SUBSTRATE FOR LATER USE

4306 FEED A COATED SUBSTRATE INTO A PRINTING MEANS FOR PRINTING INK ONTO THE SUBSTRATE

4308 STACK THE COATED SUBSTRATES AFTER PRINTING THEREON

4310 APPLY RF ENERGY TO THE STACK

4312 NIP THE STACK TO ASSURE A GOOD BOND

FIG.43

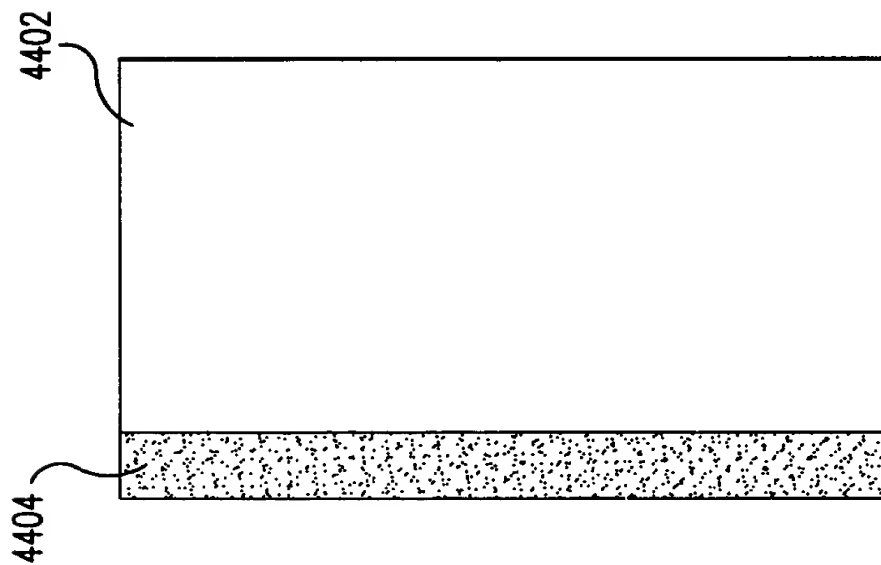


FIG. 44

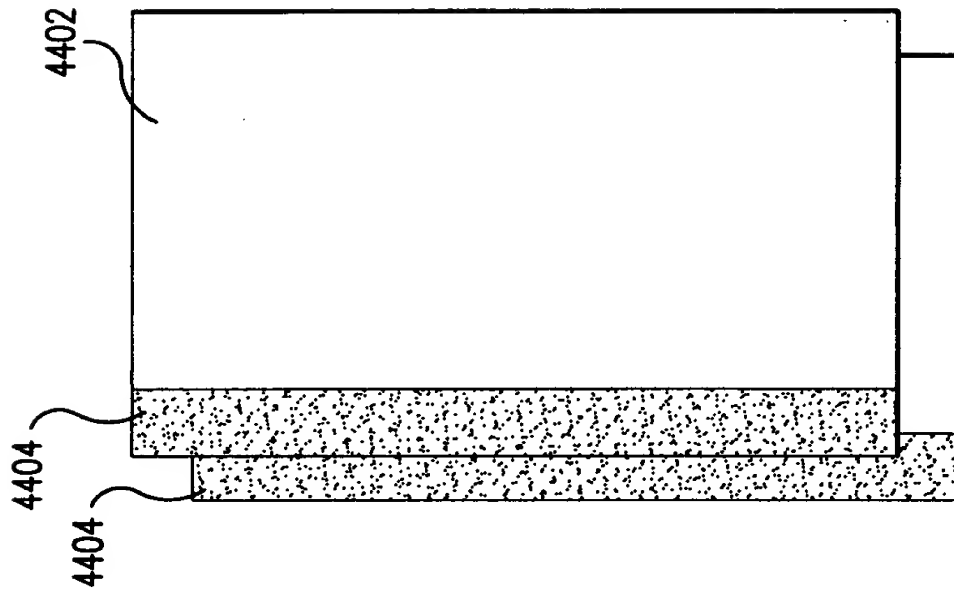


FIG. 45

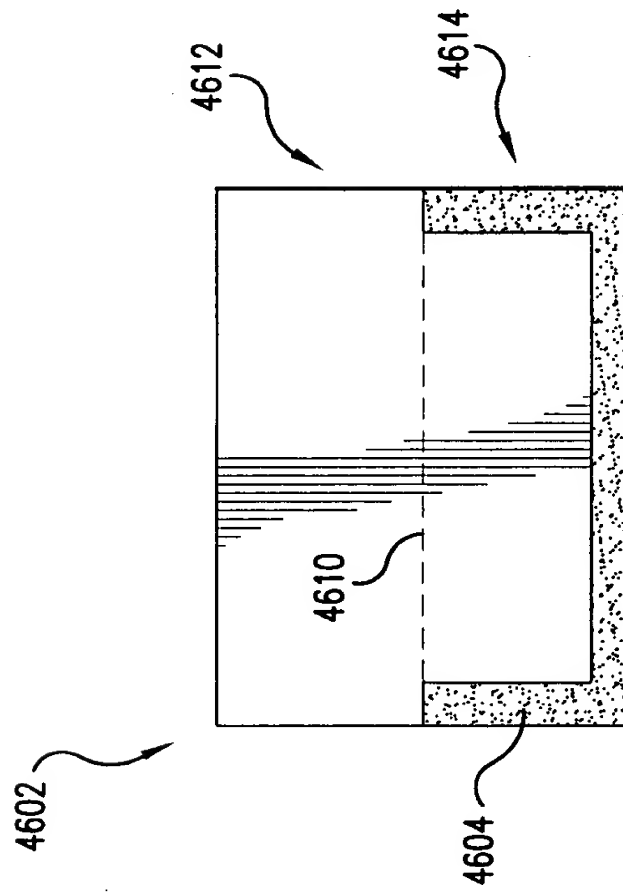


FIG. 46

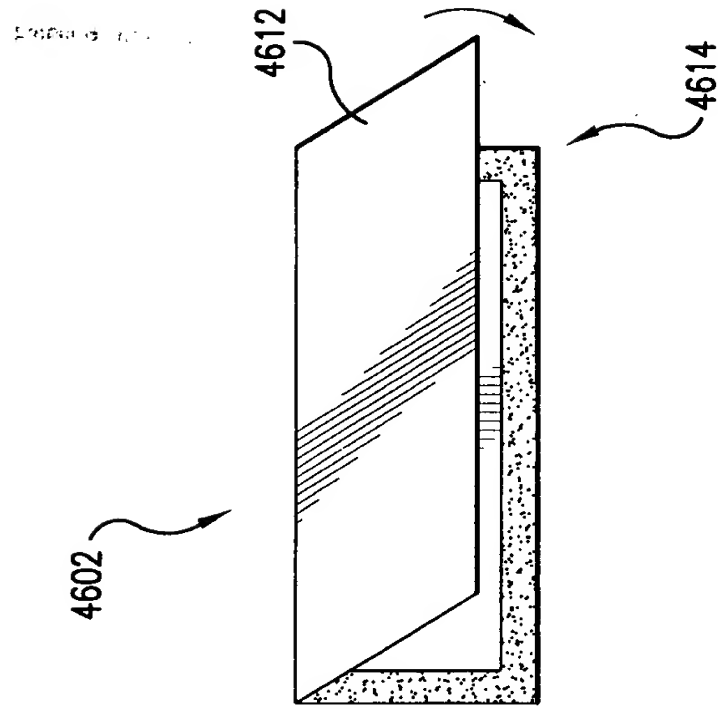


FIG. 47

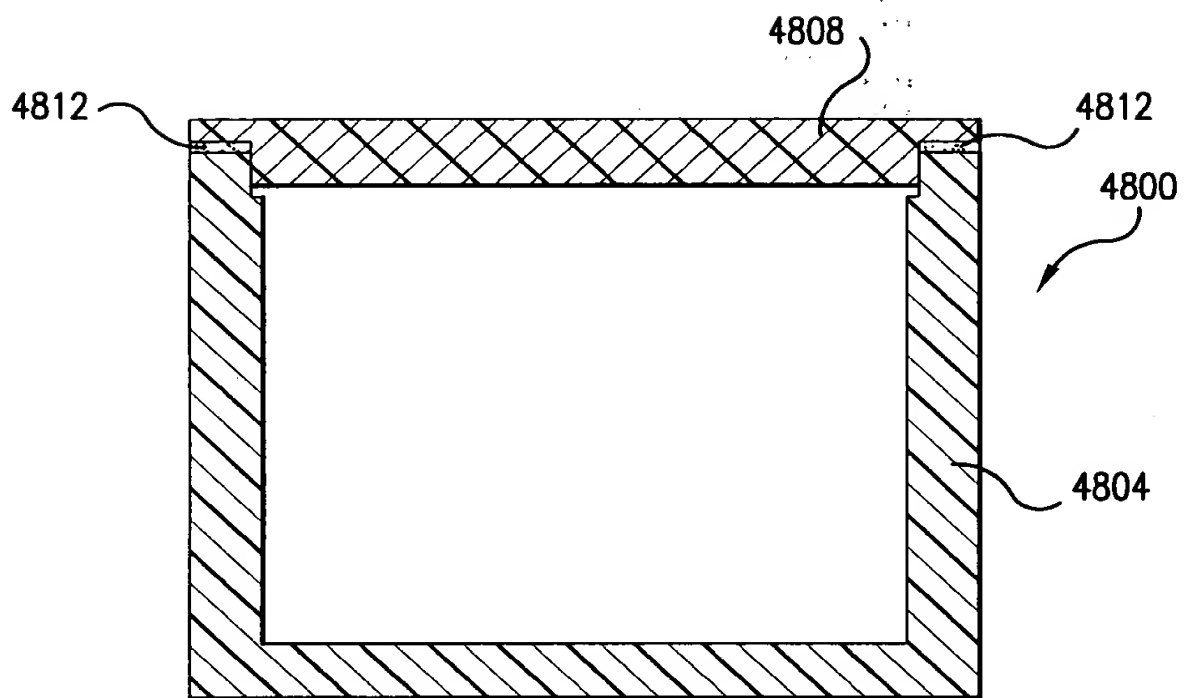


FIG.48

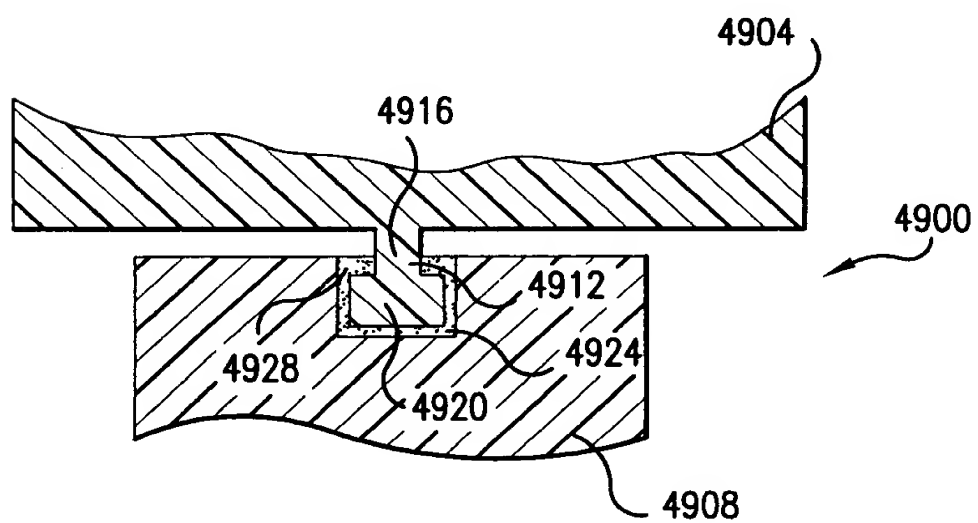


FIG.49

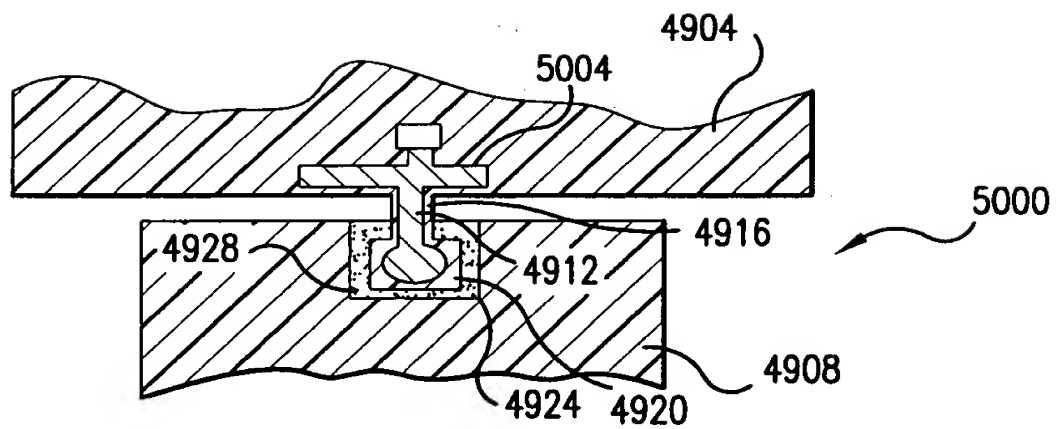


FIG.50

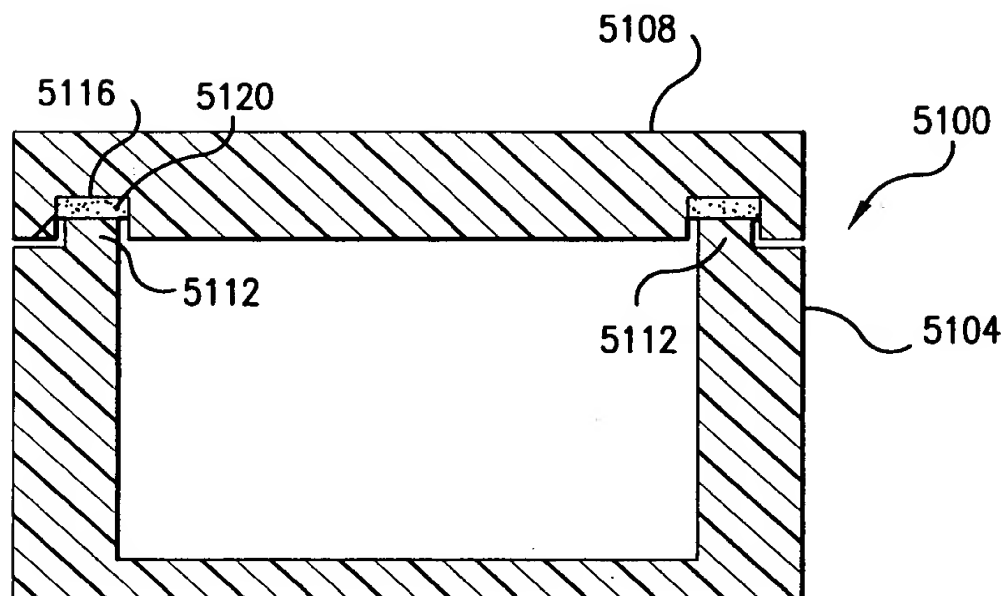


FIG.51

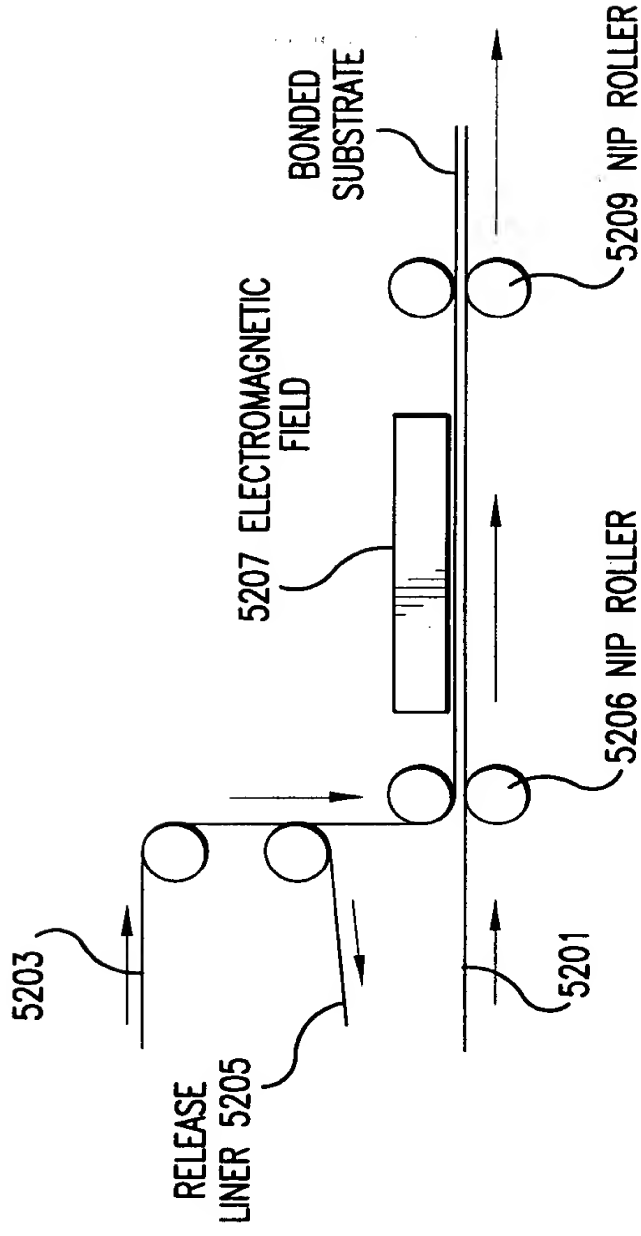


FIG.52

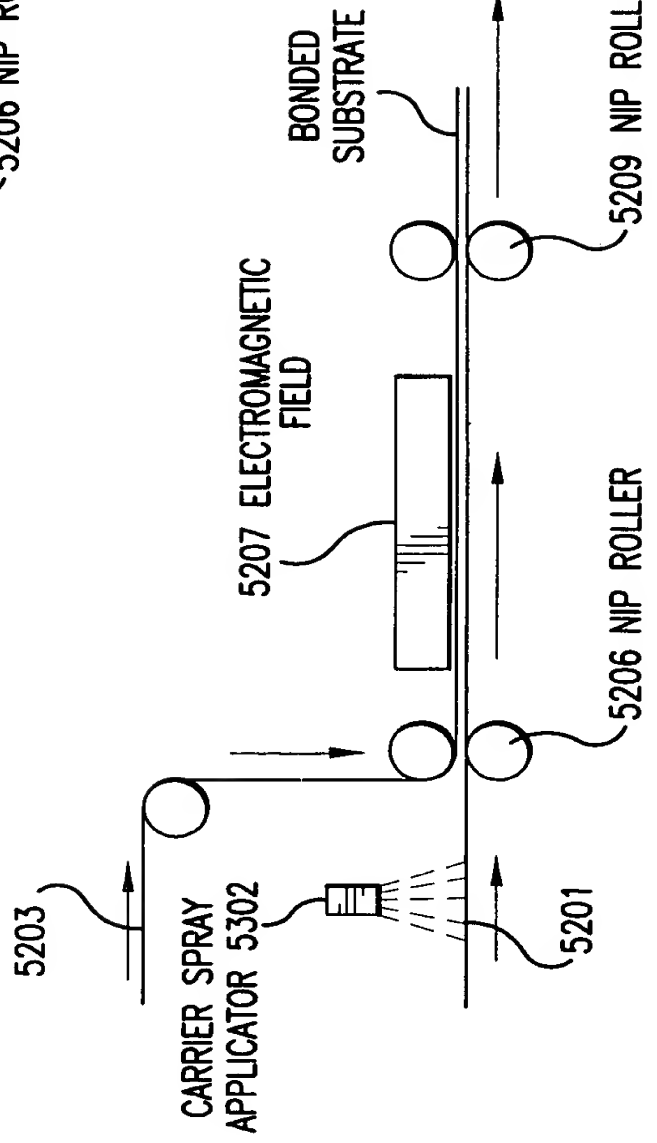


FIG.53

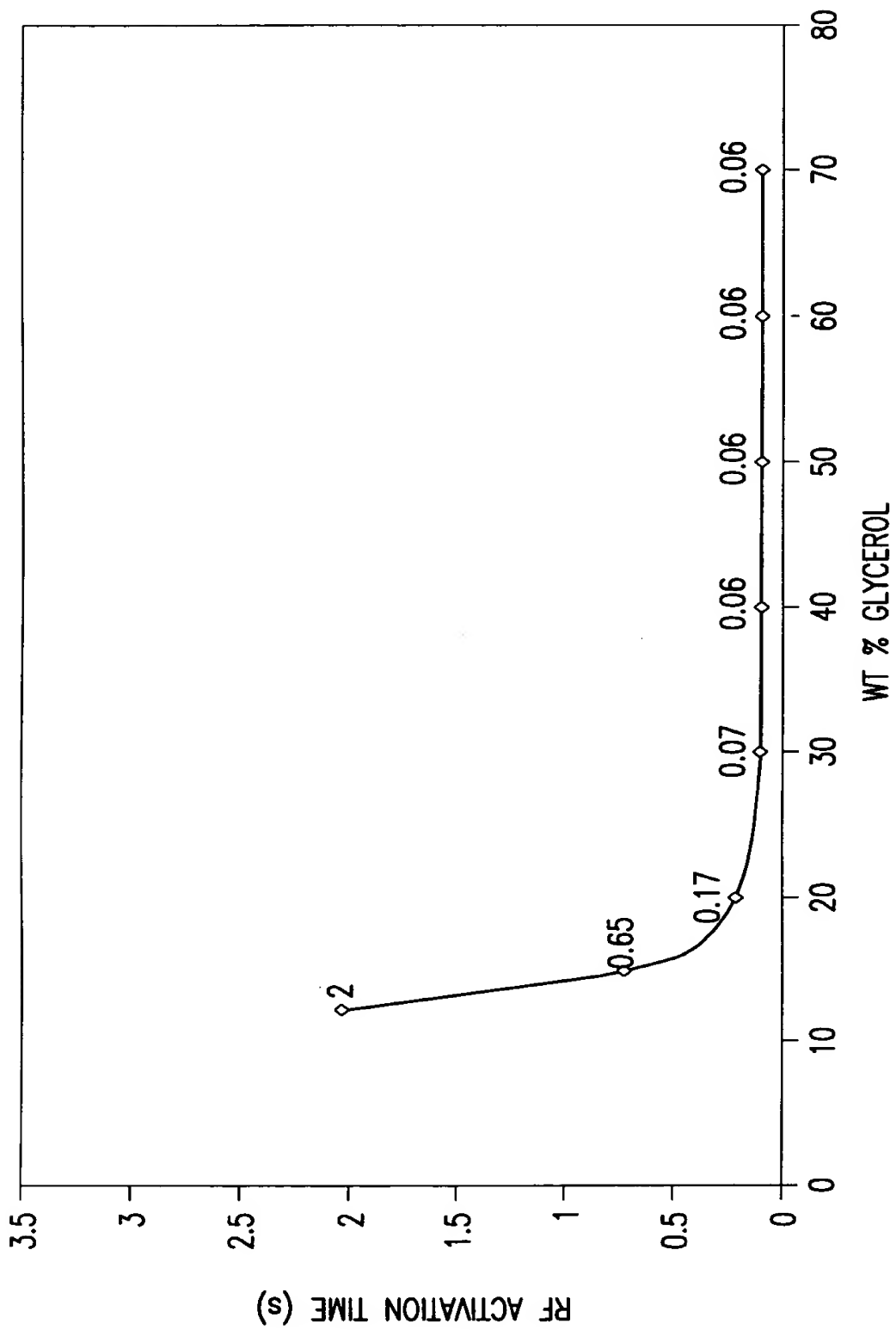


FIG. 54

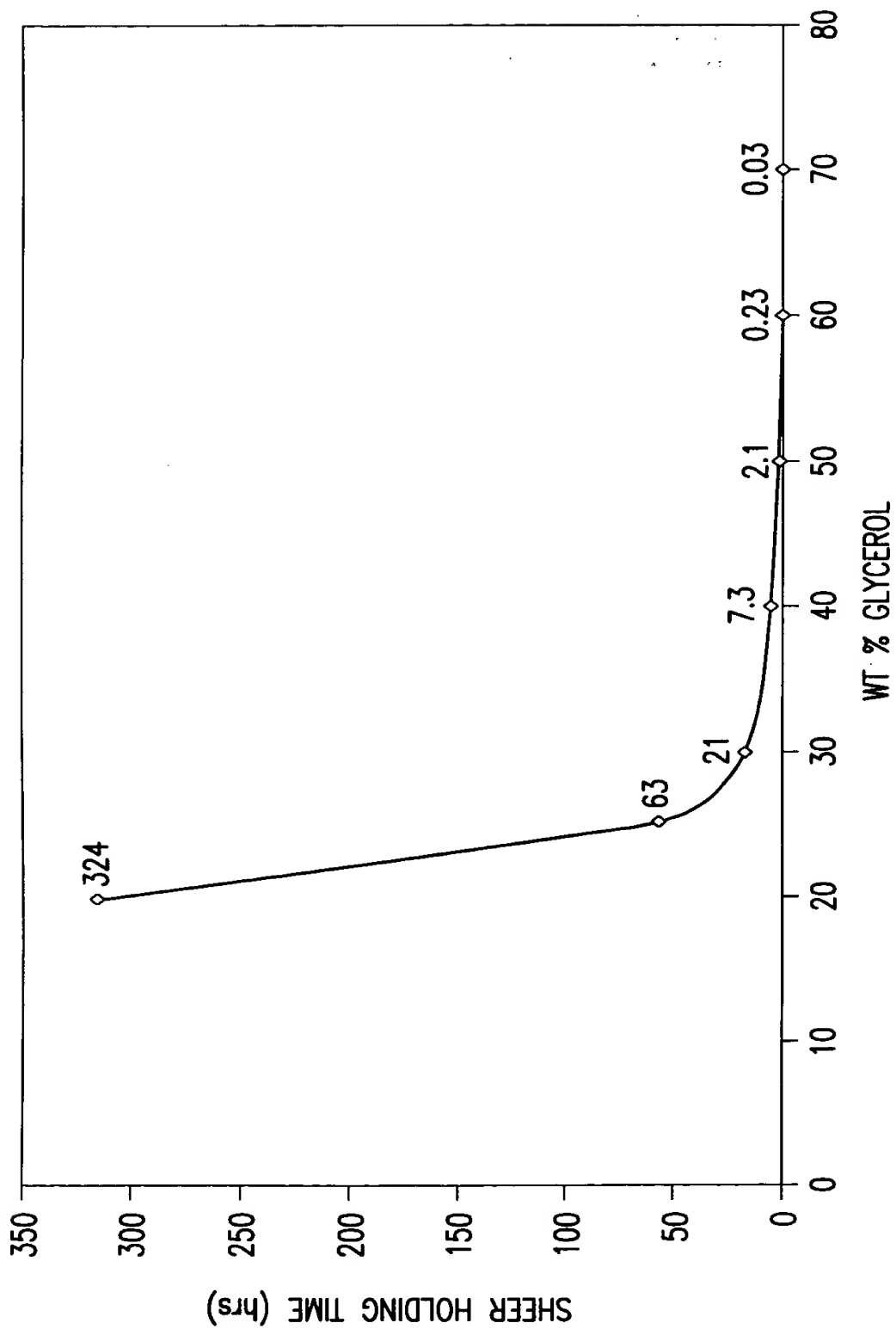


FIG. 55

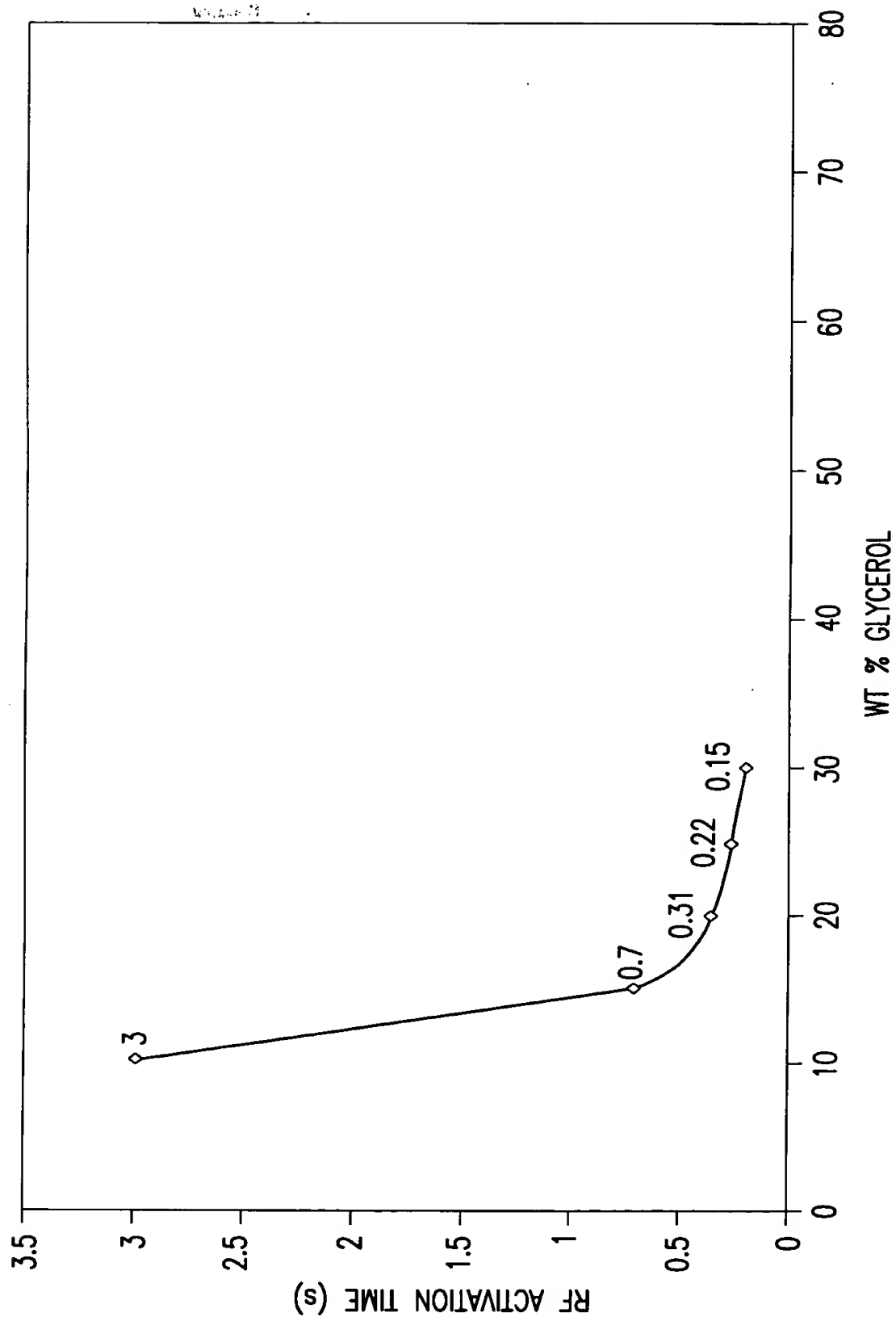


FIG. 56

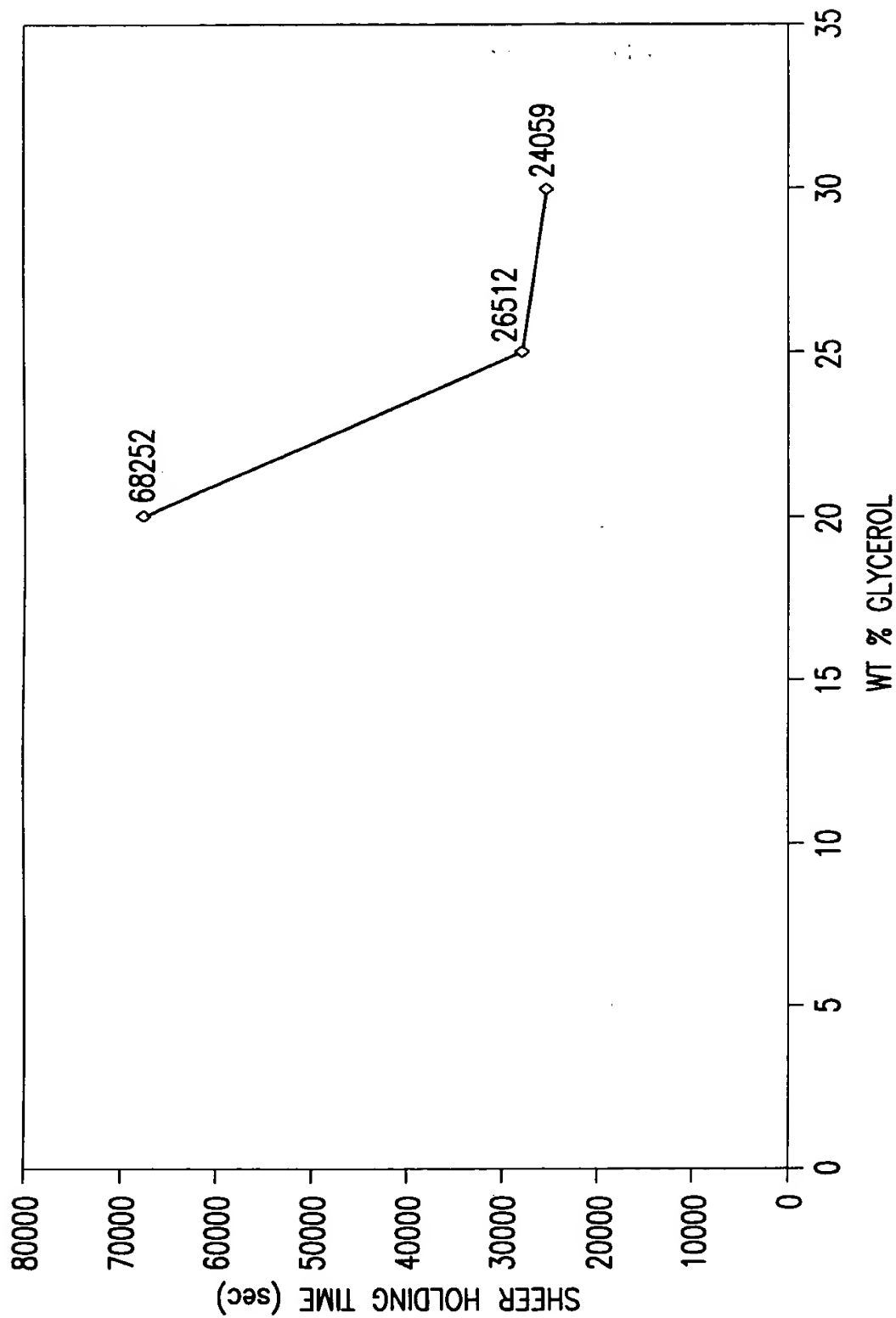


FIG.57

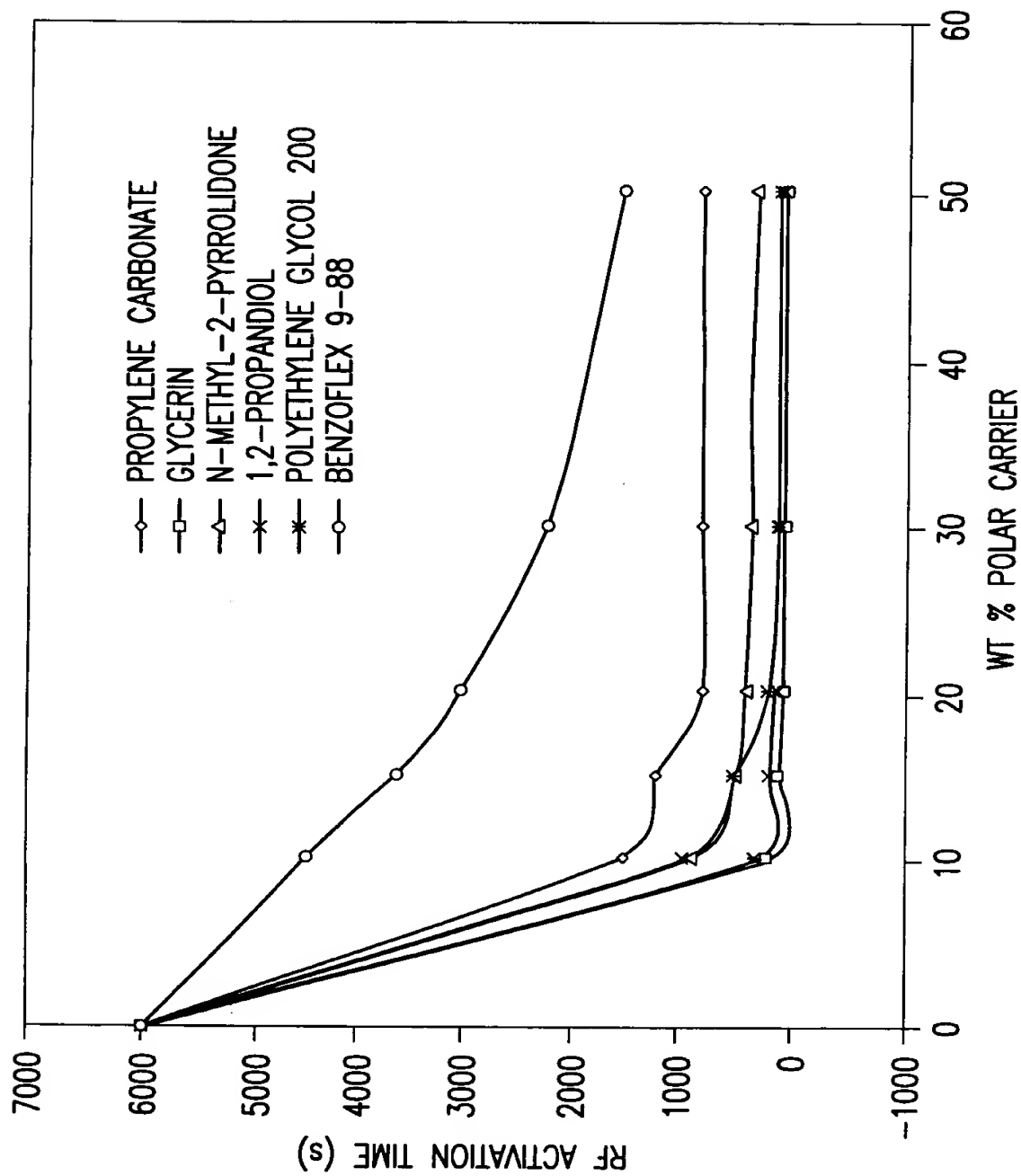


FIG.58

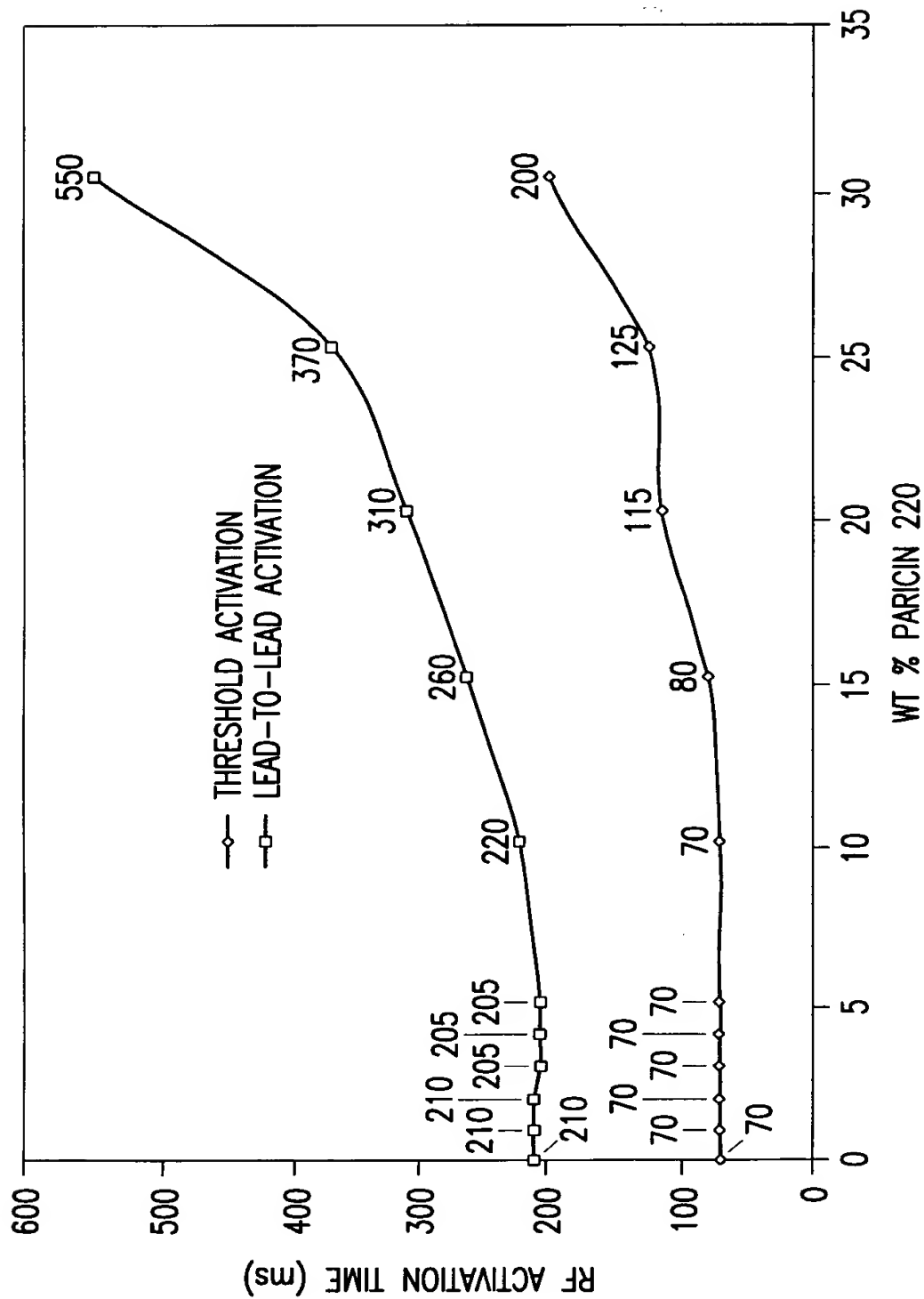


FIG.59

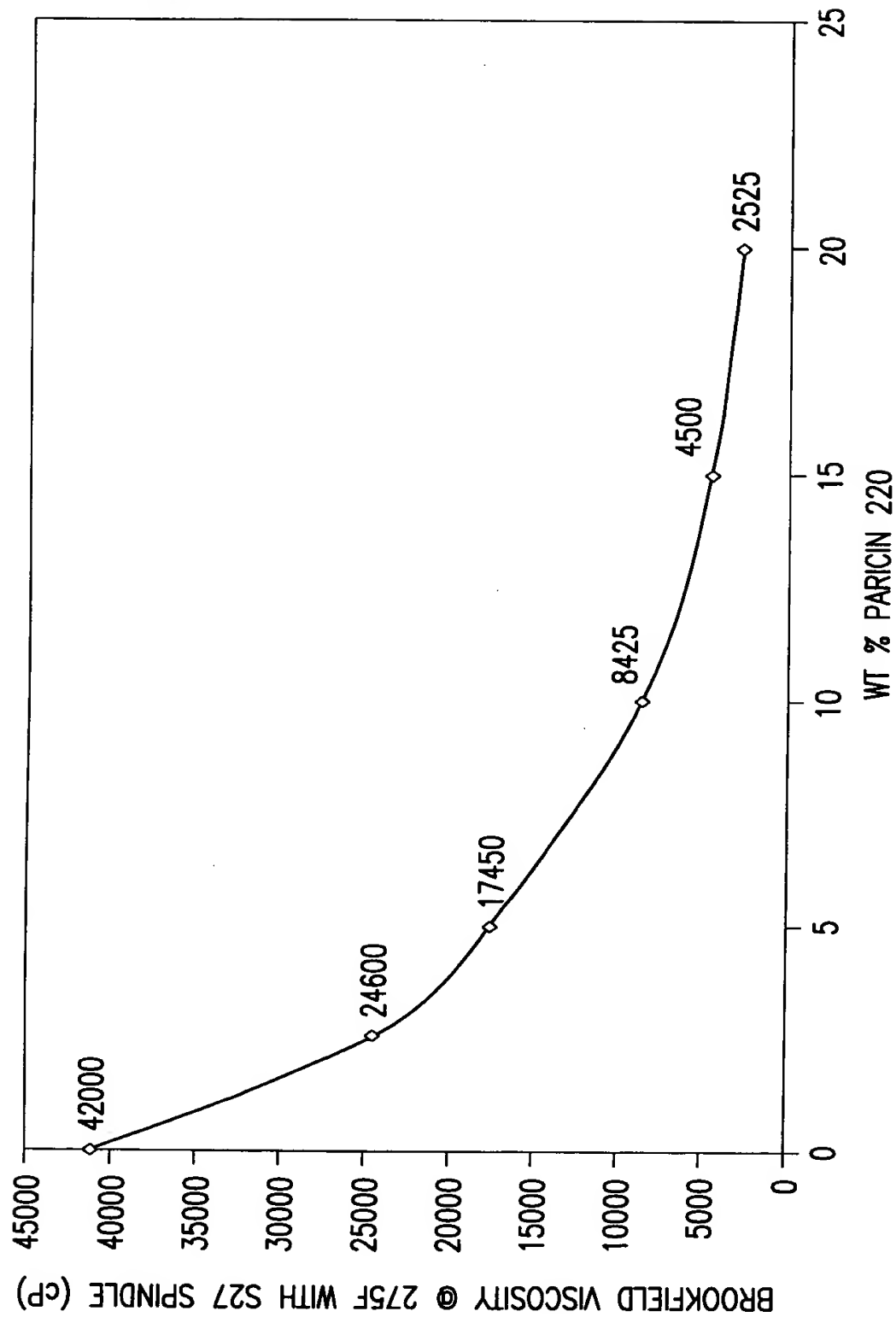


FIG.60

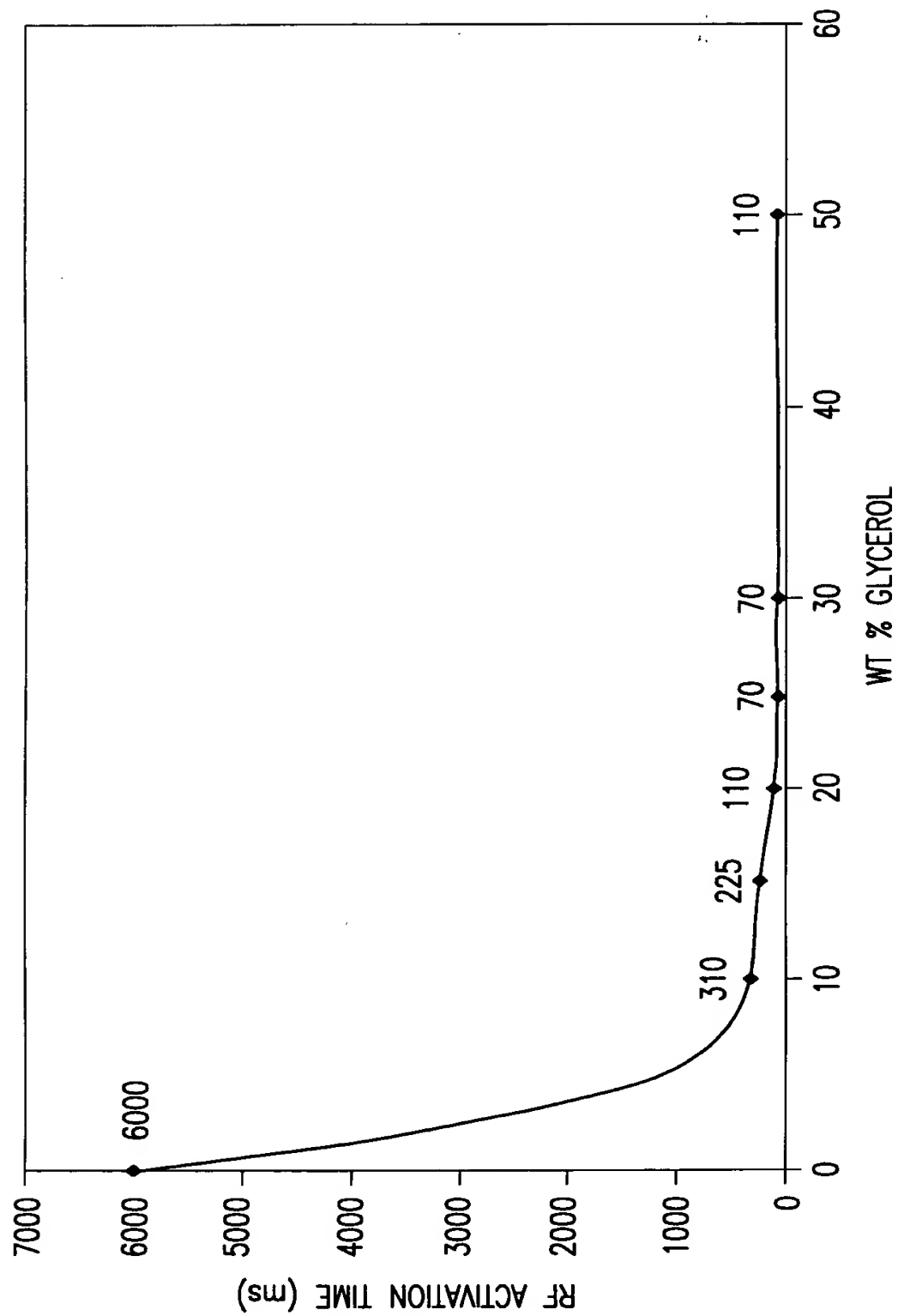


FIG. 61



FIG. 63

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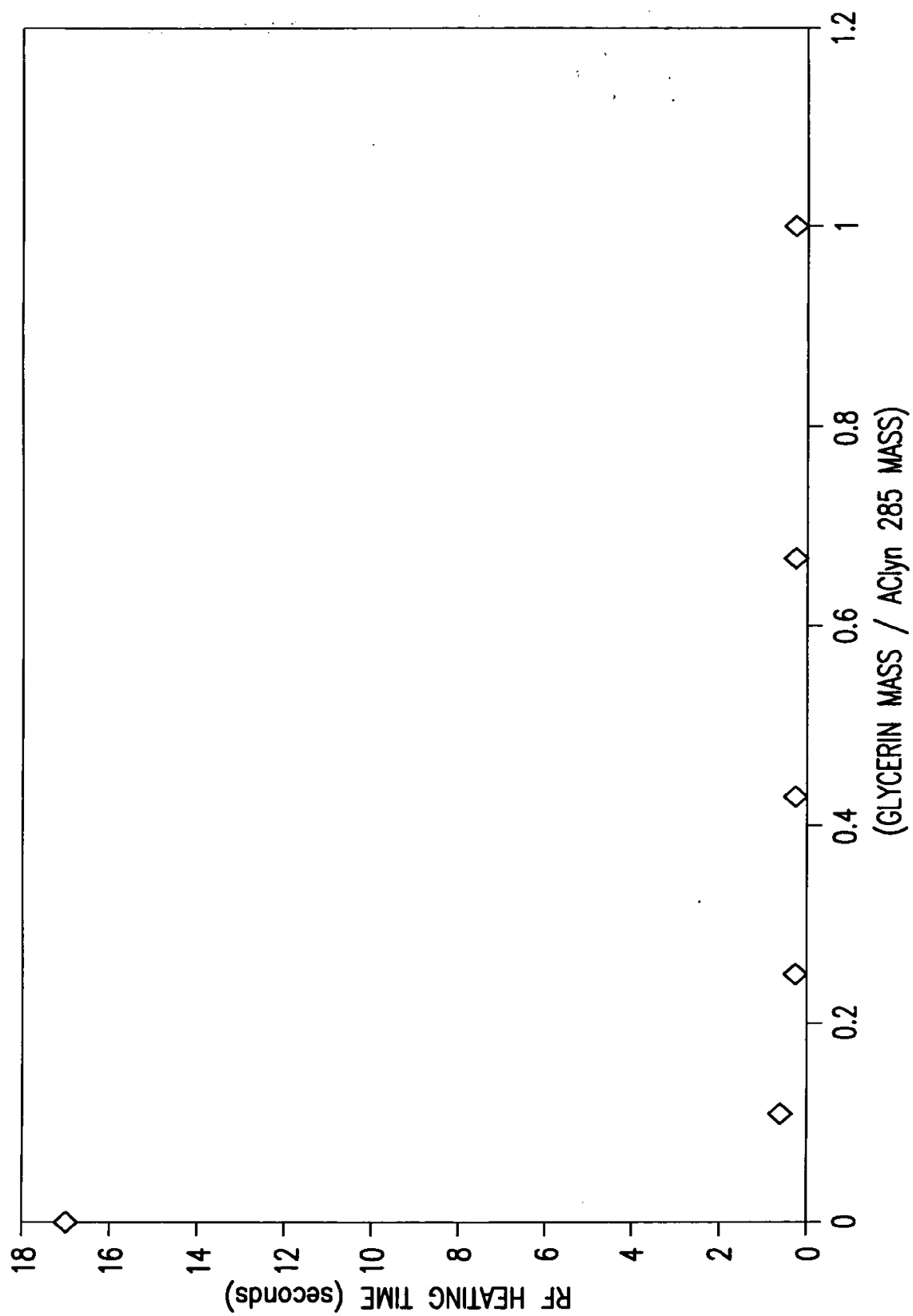


FIG.65

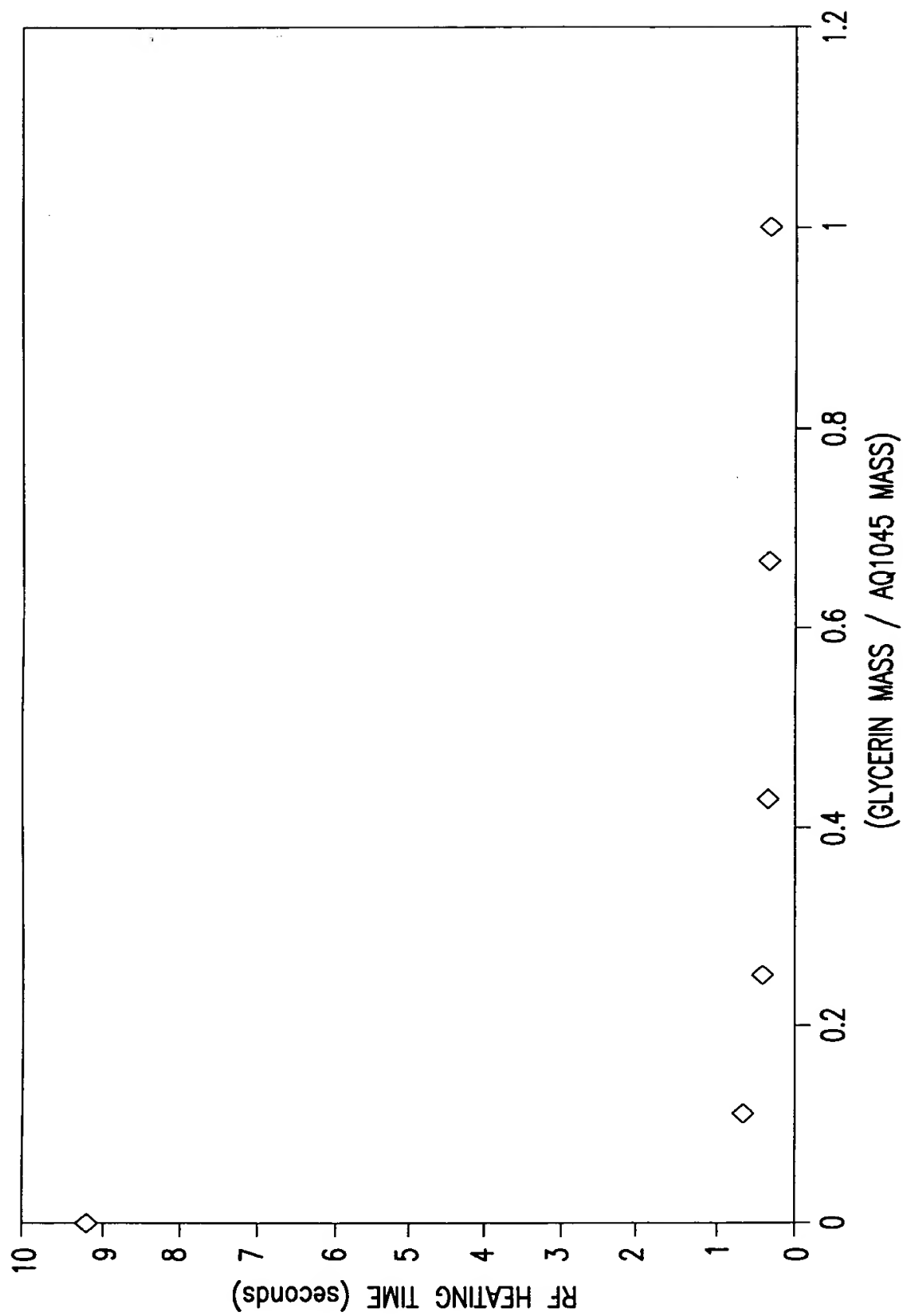


FIG.66

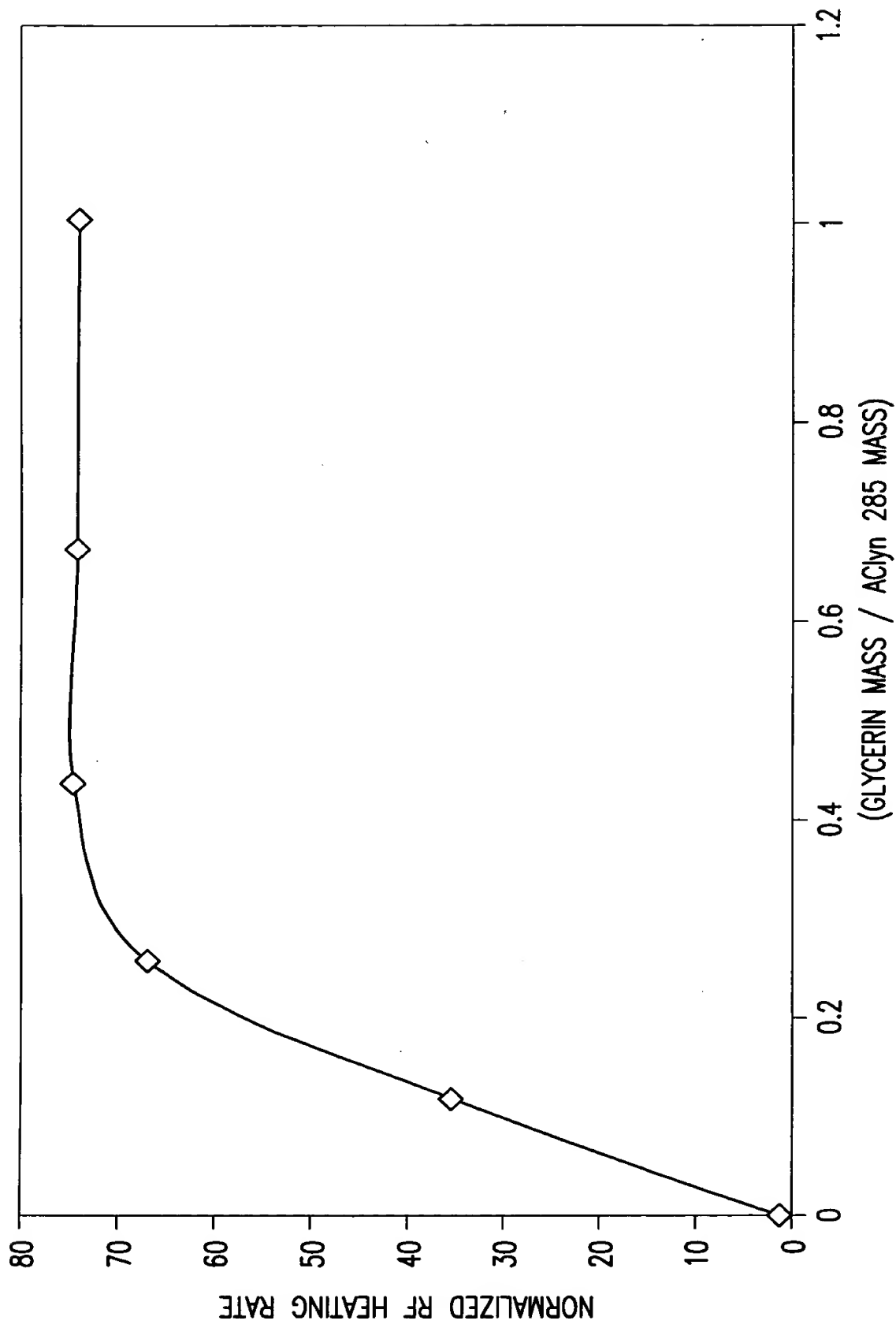


FIG.67

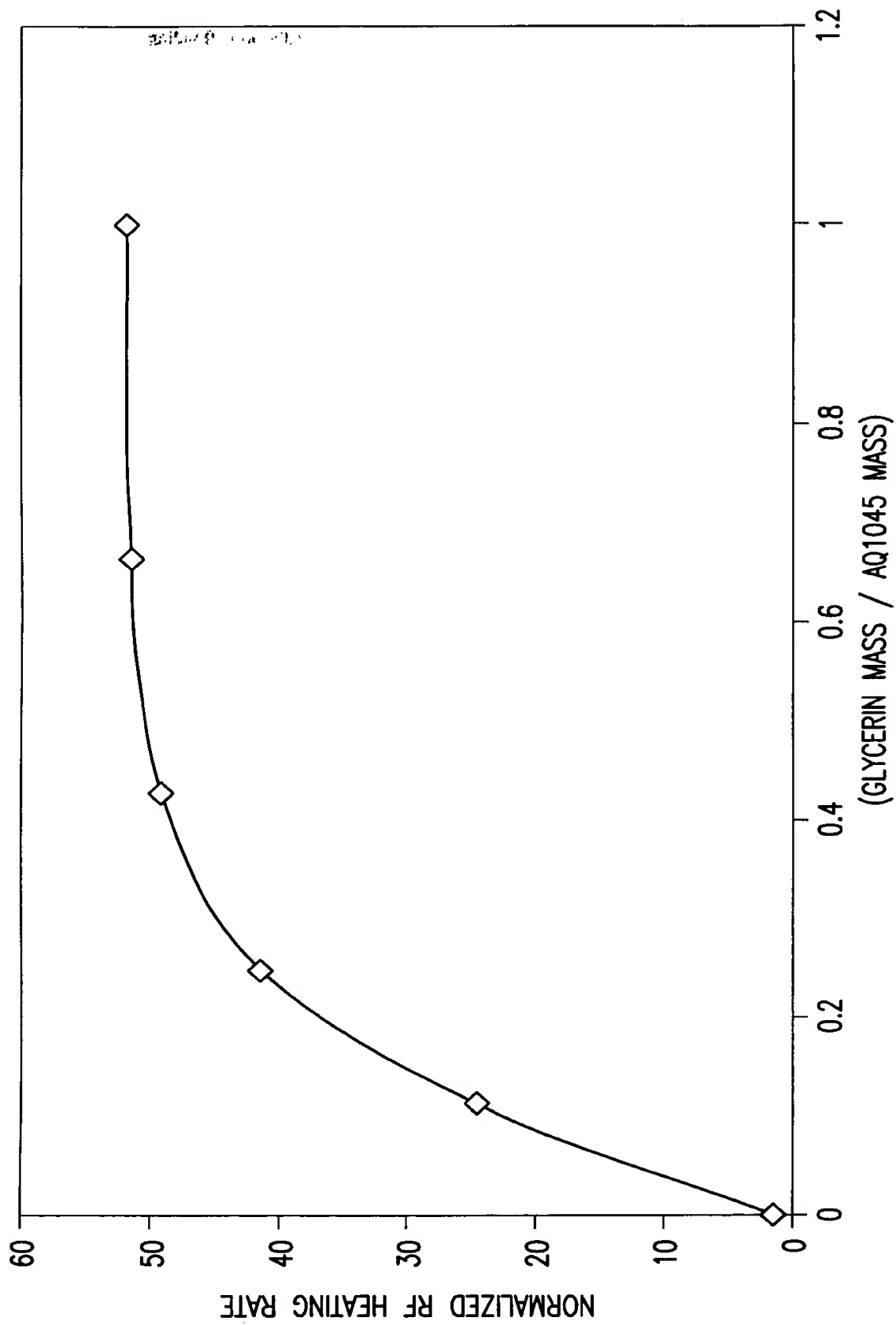


FIG.68

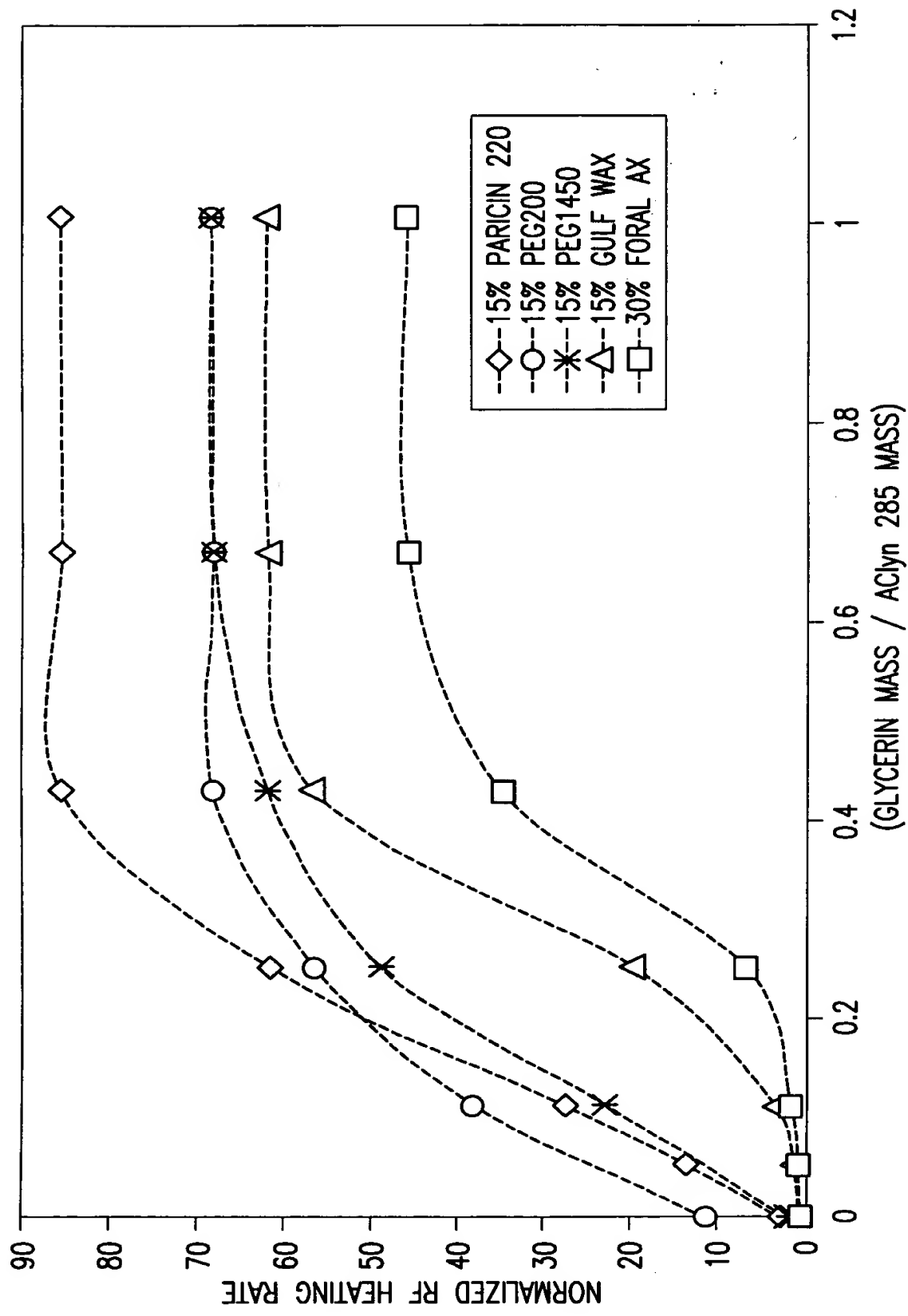


FIG.69

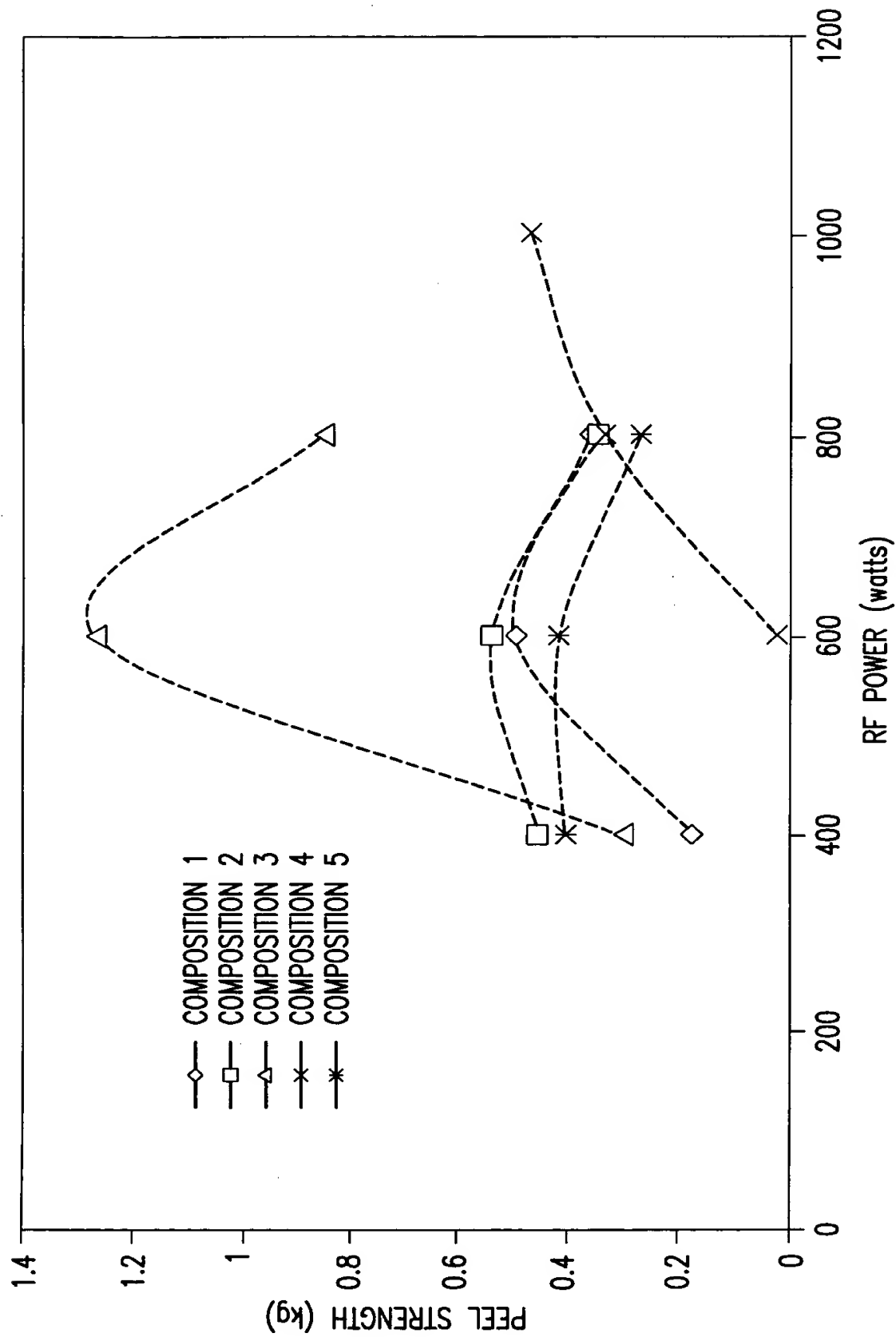


FIG.70